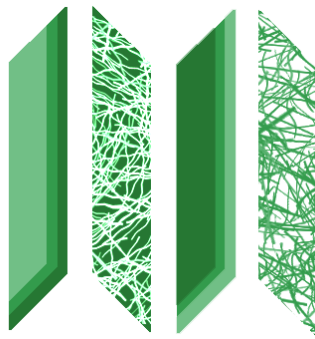


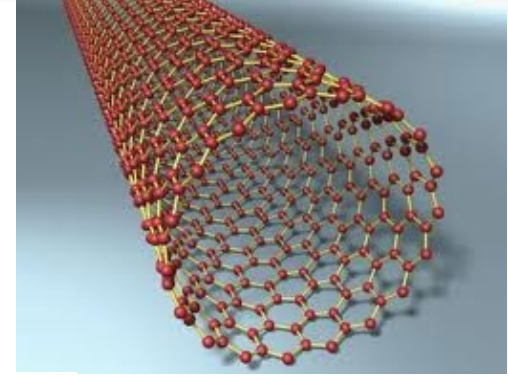


Aalto University



IRENA

Indium Replacement by
Single-Walled Carbon
Nanotube Thin Films



Japan Science and Technology Agency

IRENA project: Indium replacement by single-walled carbon nanotube thin films

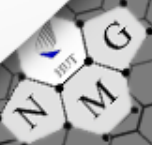
Prof. Dr. Esko I. Kauppinen

Department of Applied Physics, Aalto University School of Science

esko.kauppinen@aalto.fi

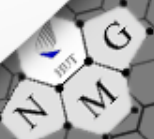
The University of Tokyo, Tokyo, Japan

February 25th, 2015



Content

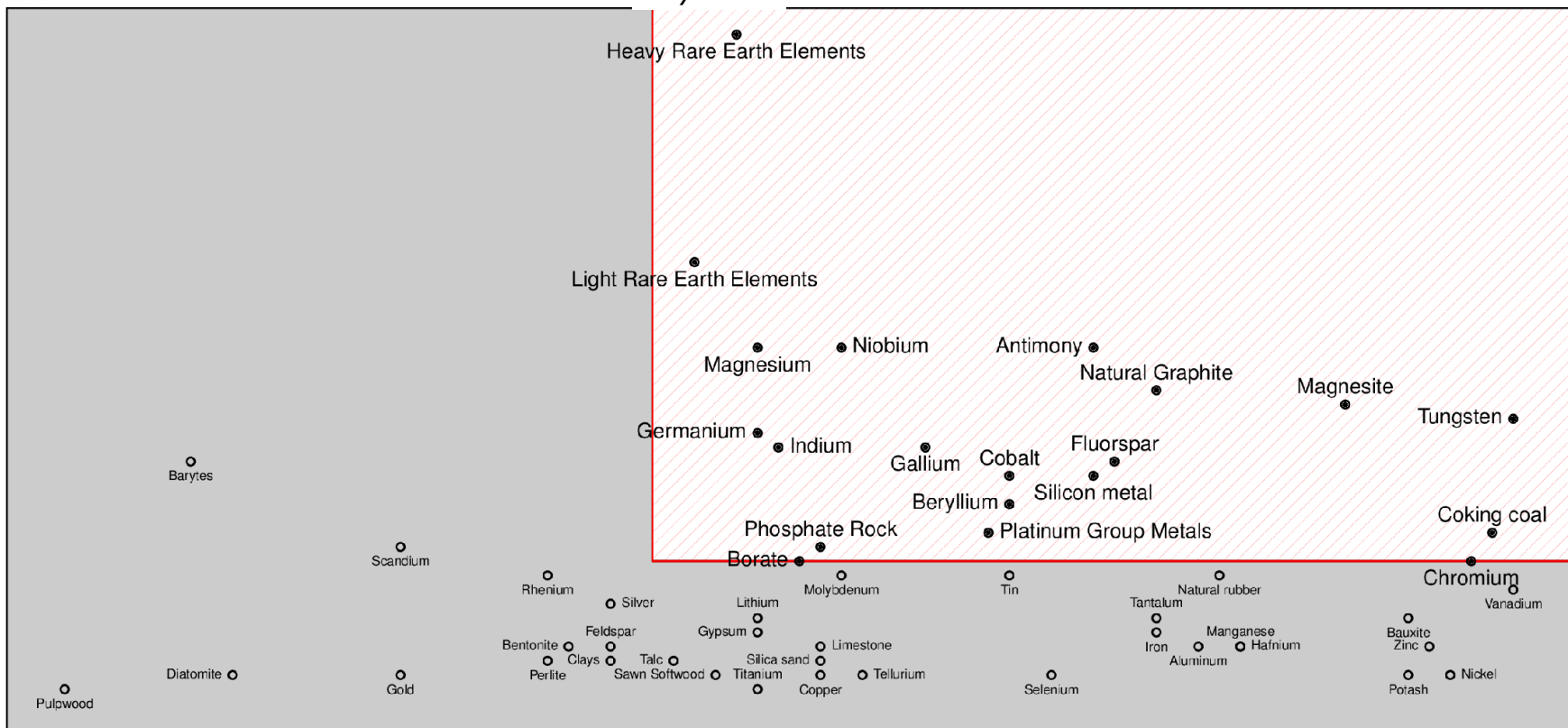
- **The need** to replace Indium and Gallium in transparent conductors (TCF) and thin film transistor (TFT): carbon nanotubes as novel materials for flexible, transparent and stretchable electronics ?
- **Project objectives:** meet ITO (indium-tin oxide) TCF and IGZO (indium-zinc-gallium oxide) TFT specs with flexible SWNT thin films
- **Partners:** 3 from EU and 3 from Japan
- **Main results** for TCF, TFTs and solar cells
- **Future plans** – how to use the results



REPORT ON CRITICAL RAW MATERIALS FOR THE EU

Report of the Ad hoc Working Group on defining critical raw materials
May 2014

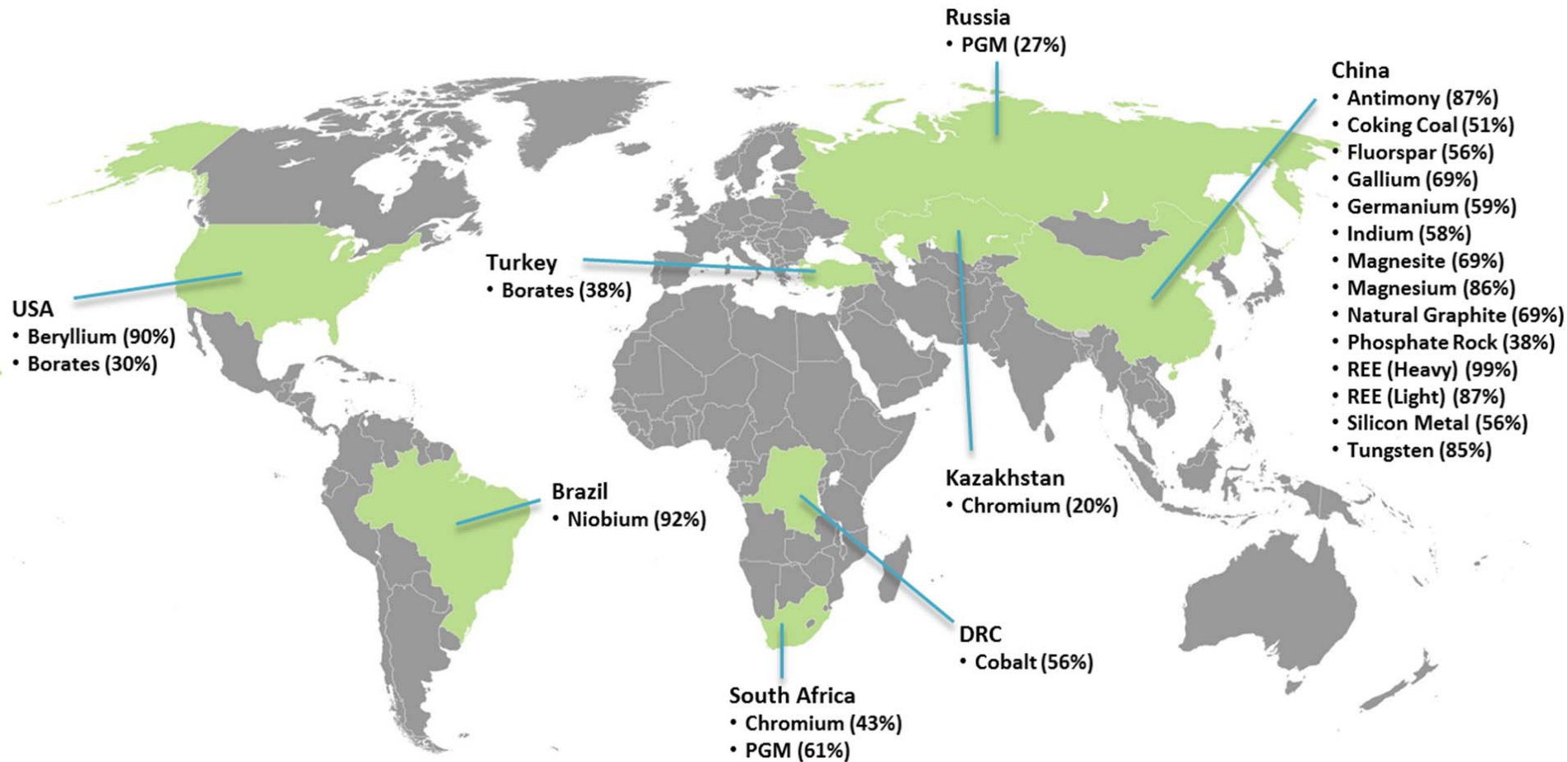
Supply risk



Economic importance

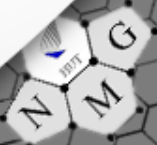
Antimony	Beryllium	Borates	Chromium	Cobalt	Coking coal	Fluorspar
Gallium	Germanium	Indium	Magnesite	Magnesium	Natural Graphite	Niobium
PGMs	Phosphate Rock	REEs (Heavy)	REEs (Light)	Silicon Metal	Tungsten	





EIT's 2014 Call for KICs Proposals

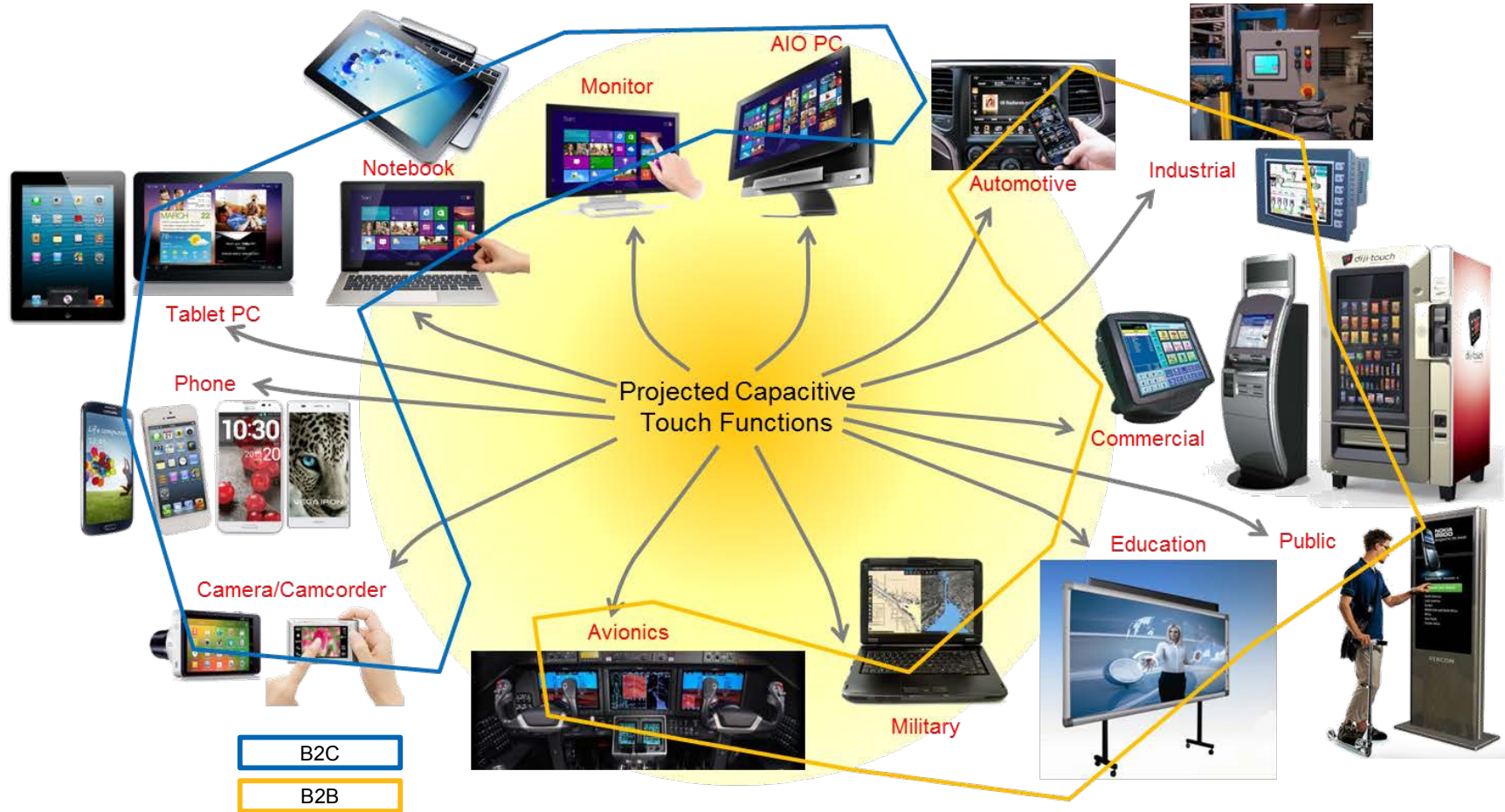
EIT Raw Materials was designated as an EIT Knowledge and Innovation Community (KIC) by the EIT Governing Board on 09 December 2014. The below provides some information about the challenges the KIC will address in the field of raw materials (sustainable exploration, extraction, processing, recycling and substitution) and the impact it will generate.



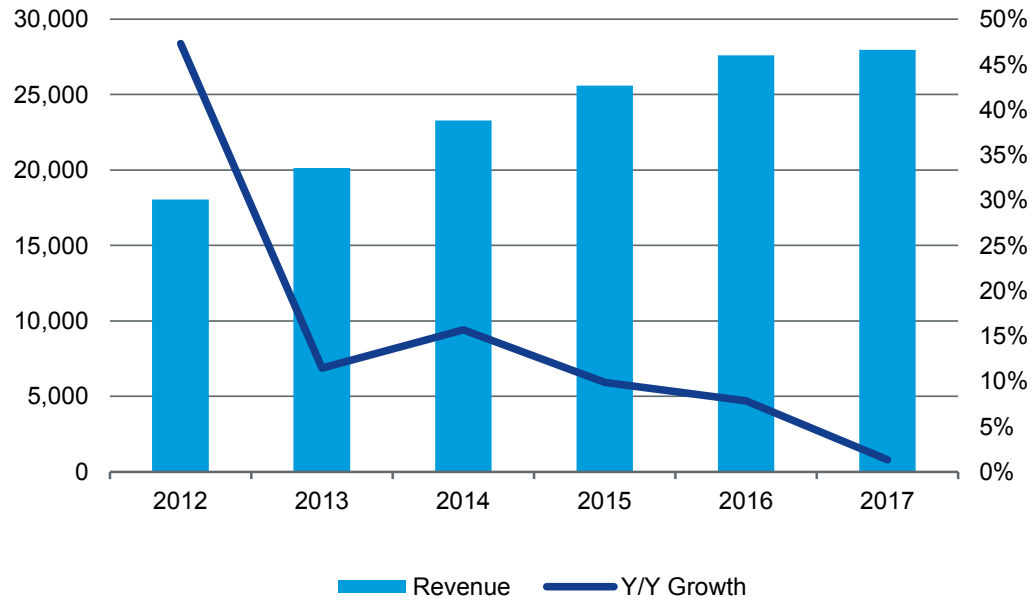
Indium in touch sensors

- Touch technology is increasingly applied to all types of electronic devices used daily.
- With projected capacitive touch sensors being applied as almost a standard to smartphones and other consumer electronics, capacitive touch technology is replacing other technologies used in almost every touch-sensor application.

Touch everywhere

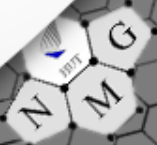


Overall touch panel market forecast (\$ million)

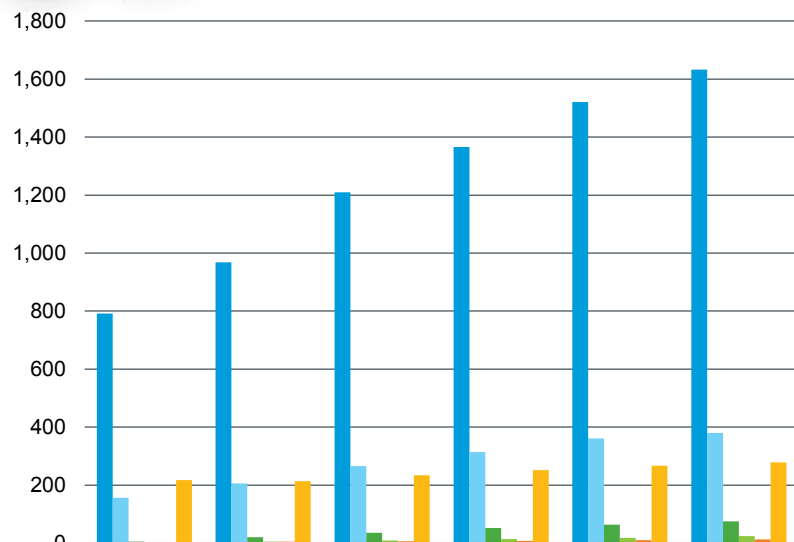


Overall touch panel market forecast (\$ million)

	2012	2013	2014	2015	2016	2017	CAGR
Revenue	18,054	20,125	23,282	25,586	27,591	27,960	9.1%
Y/Y Growth	47.3%	11.5%	15.7%	9.9%	7.8%	1.3%	

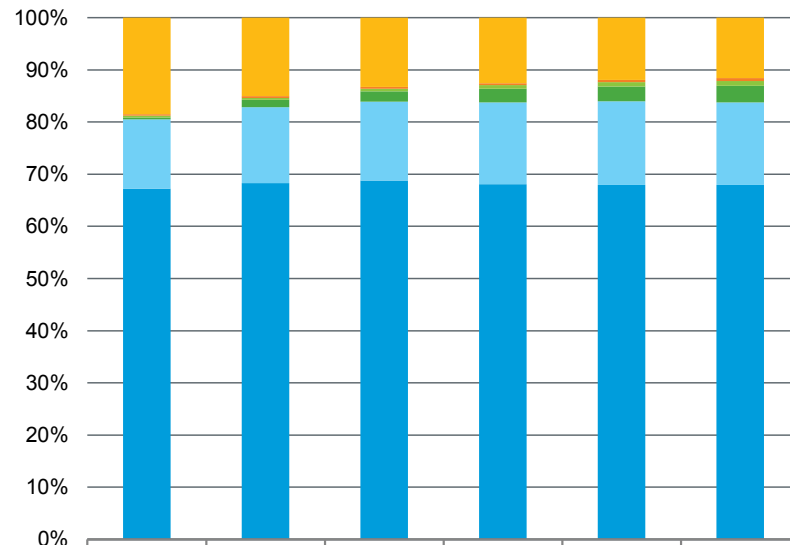


Touch panel market forecast by major application (Unit: million)

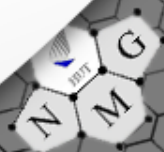


	2012	2013	2014	2015	2016	2017
■ Mobile Phone	792.0	967.7	1,210.0	1,366.2	1,521.2	1,632.4
■ Tablet PC	156.0	205.5	265.6	314.4	360.4	380.0
■ Notebook PC	4.6	20.3	35.2	51.5	63.0	75.3
■ LCD Monitor	4.2	5.0	8.4	14.1	17.9	23.6
■ AIO PC	3.7	4.6	6.3	7.9	10.4	12.2
■ Others	217.6	213.3	233.5	251.7	266.9	278.8

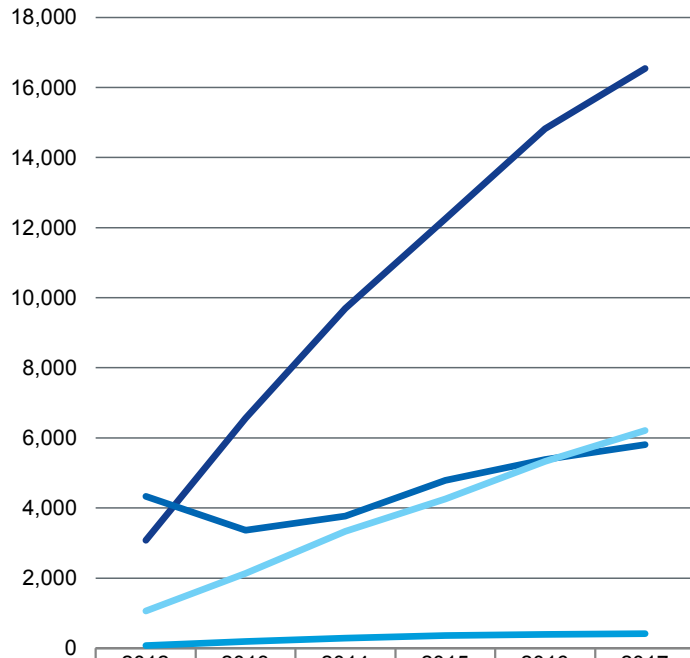
Touch panel market share by major application (%)



	2012	2013	2014	2015	2016	2017
■ Others	18%	15%	13%	13%	12%	12%
■ AIO PC	0%	0%	0%	0%	0%	1%
■ LCD Monitor	0%	0%	0%	1%	1%	1%
■ Notebook PC	0%	1%	2%	3%	3%	3%
■ Tablet PC	13%	15%	15%	16%	16%	16%
■ Mobile Phone	67%	68%	69%	68%	68%	68%

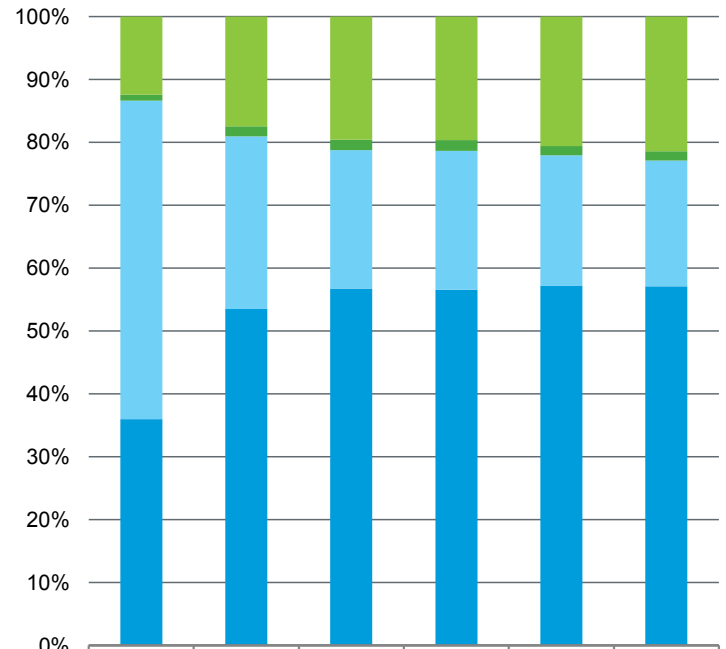


Capacitive touch panel market forecast by layer structure (Ksqm)

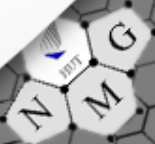


	2012	2013	2014	2015	2016	2017
Film Sensor	3,079	6,561	9,690	12,247	14,821	16,543
Glass Sensor	4,331	3,366	3,764	4,786	5,380	5,808
Hybrid Sensor	77	191	281	364	389	417
Embedded Sensor	1,062	2,139	3,338	4,252	5,333	6,205

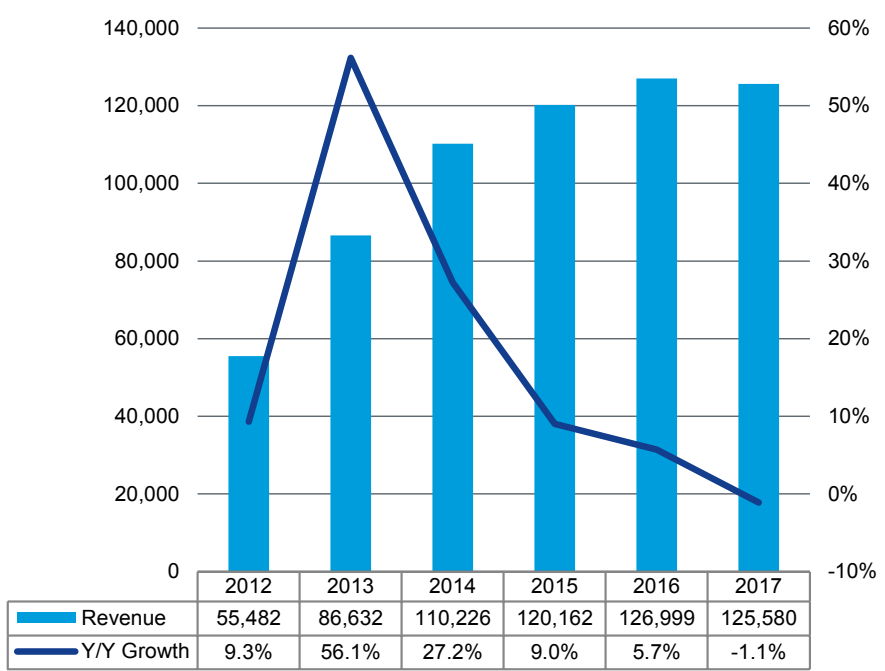
Capacitive touch panel market forecast by layer structure (%)



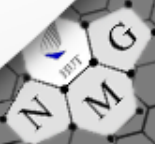
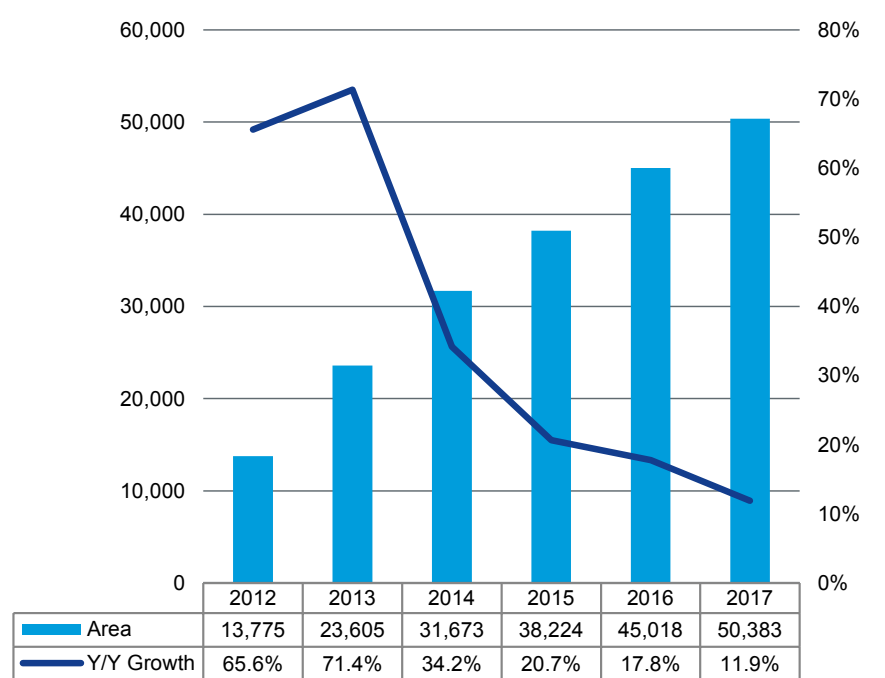
	2012	2013	2014	2015	2016	2017
Embedded Sensor	12%	17%	20%	20%	21%	21%
Hybrid Sensor	1%	2%	2%	2%	2%	1%
Glsss Sensor	51%	27%	22%	22%	21%	20%
Film Sensor	36%	54%	57%	57%	57%	57%



Overall transparent conductive film market forecast (¥ million)

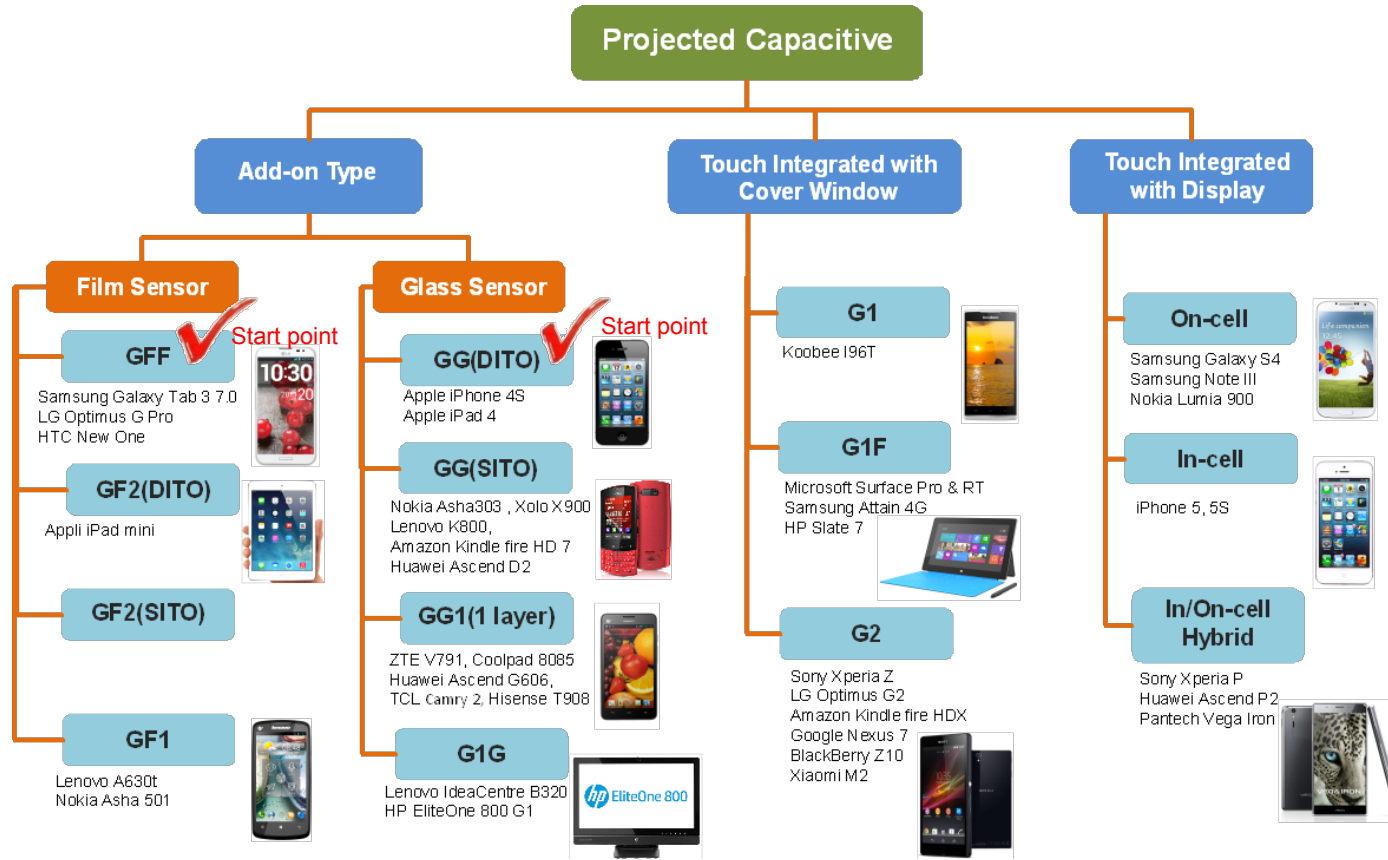


Overall transparent conductive film market forecast (Ksqm)

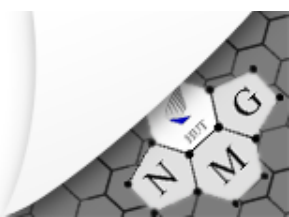


- The market initially started with glass types (GG, DITO) and film types (GFF), but currently there are more than 10 types of touch panels with different layer structures.
- Each method has its pros and cons according to the technology, production cost, client preference, and each developer's situation.

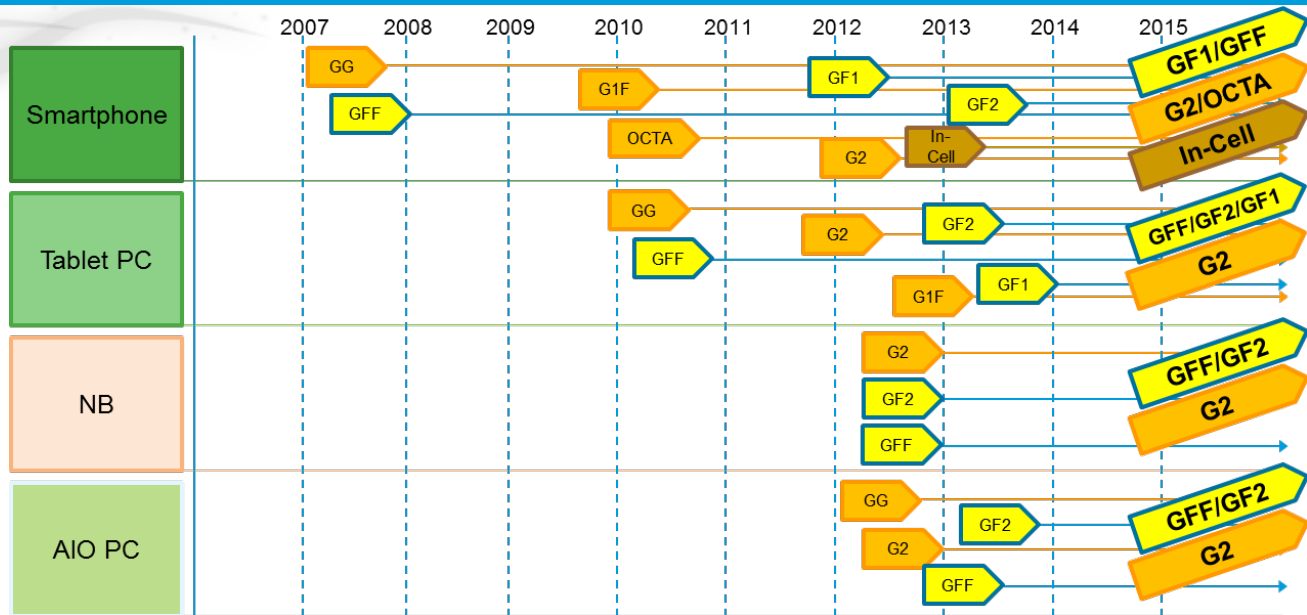
Projected capacitive touch layer types and major products of each type



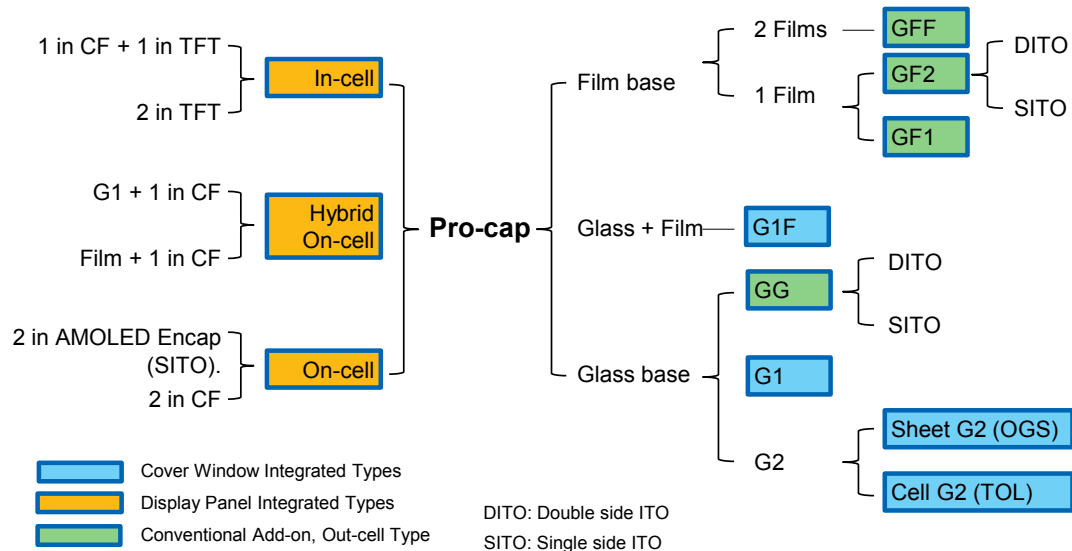
GG - cover glass+ ITO glass sensor
 GFF - cover glass + two ITO film sensors



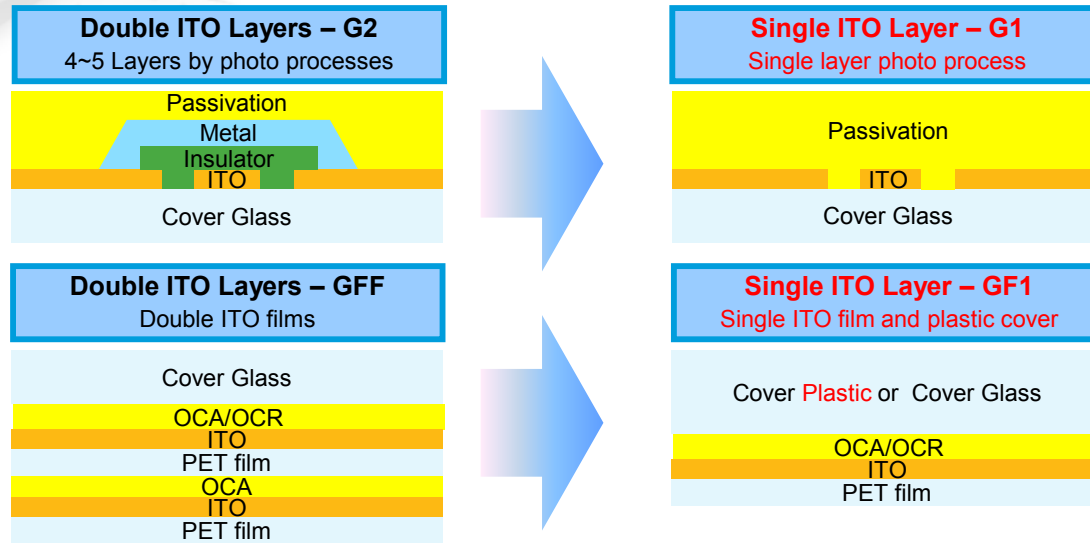
History and forecast: Projected capacitive layers by application



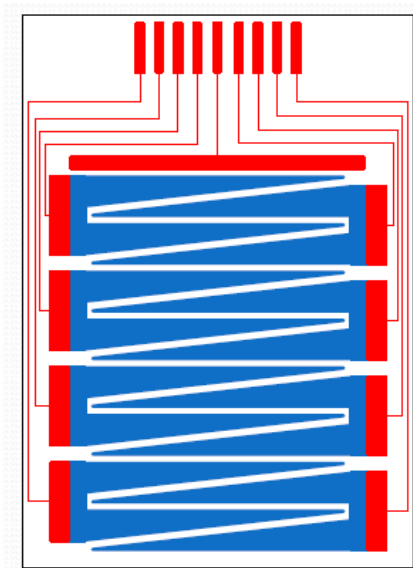
Projected capacitive touch type by layer structure



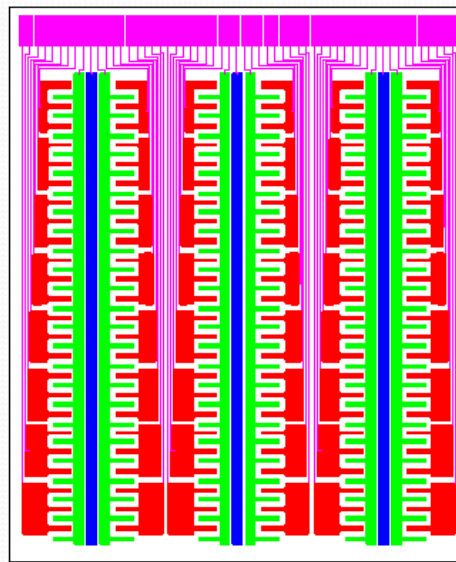
Advantages of one layer type solution over two layer type: Simpler process and lower cost



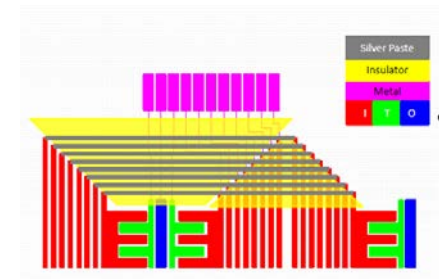
Single layer touch patterns (Without a via hole and with a via hole)



Single point + Gesture

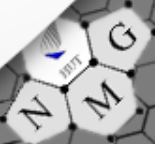
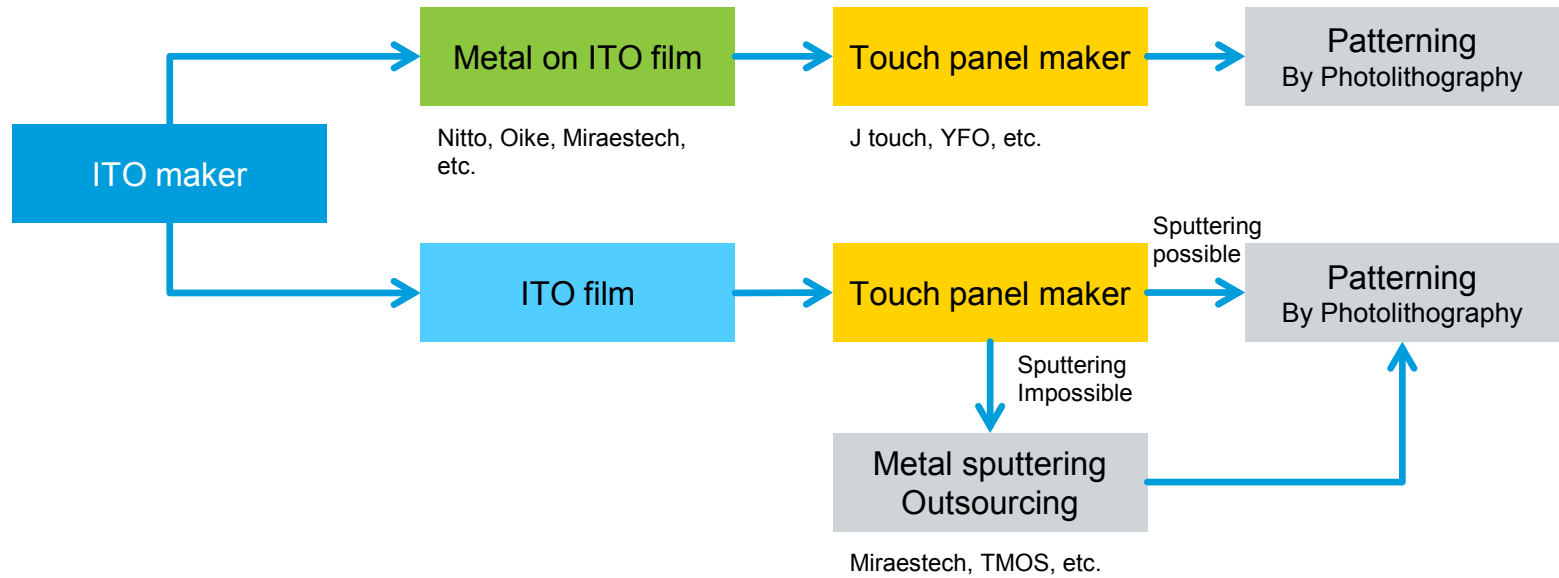
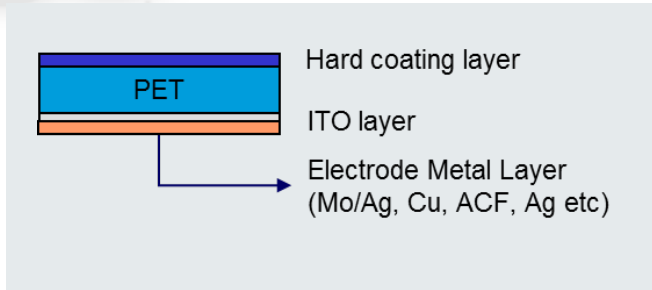


Single Layer with Multi-touch (w/o a via hole)

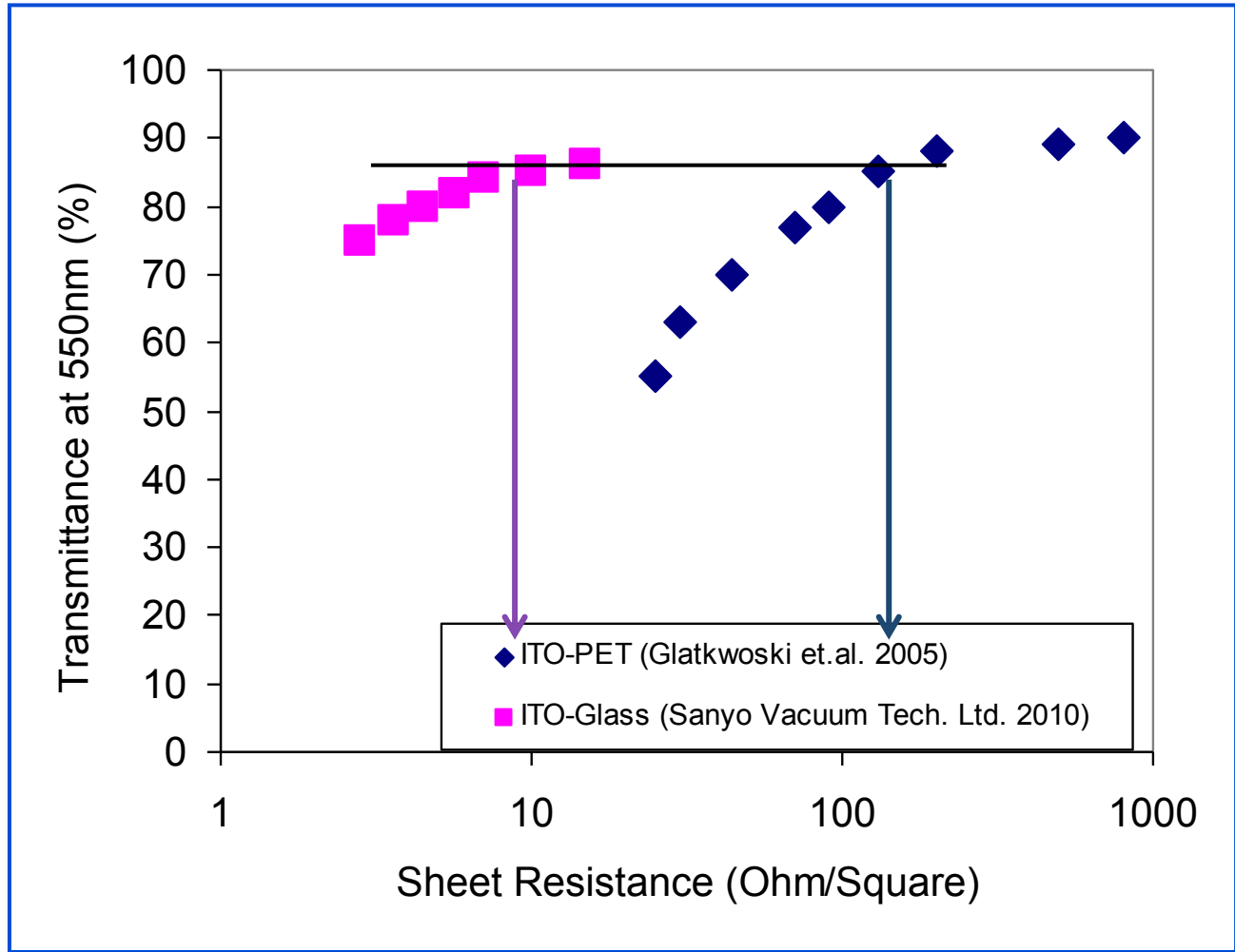


Single Layer with Multi-touch (with a via hole)

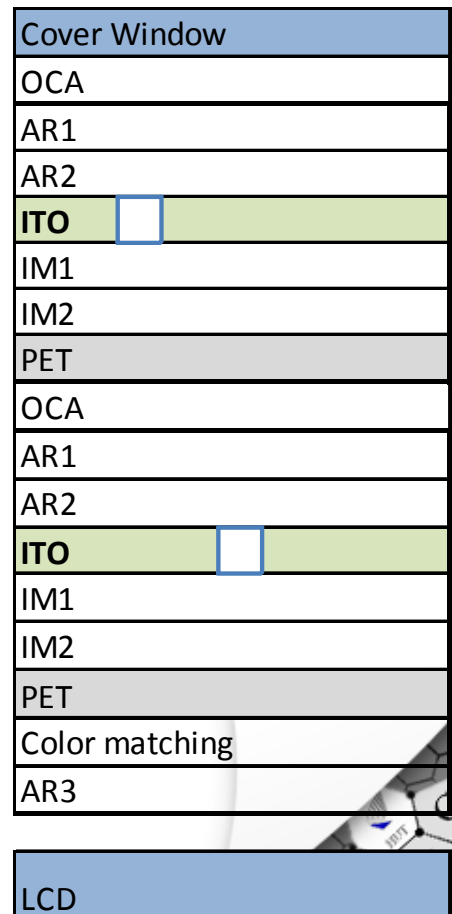
Structure and value chain of metal on ITO



ITO-on-glass (fragile) and ITO-on-PET (a bit pendable) transmittance vs. sheet resistance - NOT flexible and vacuum-processed REFLECTION and HAZE IMPORTANT ISSUES, not only sheet resistance



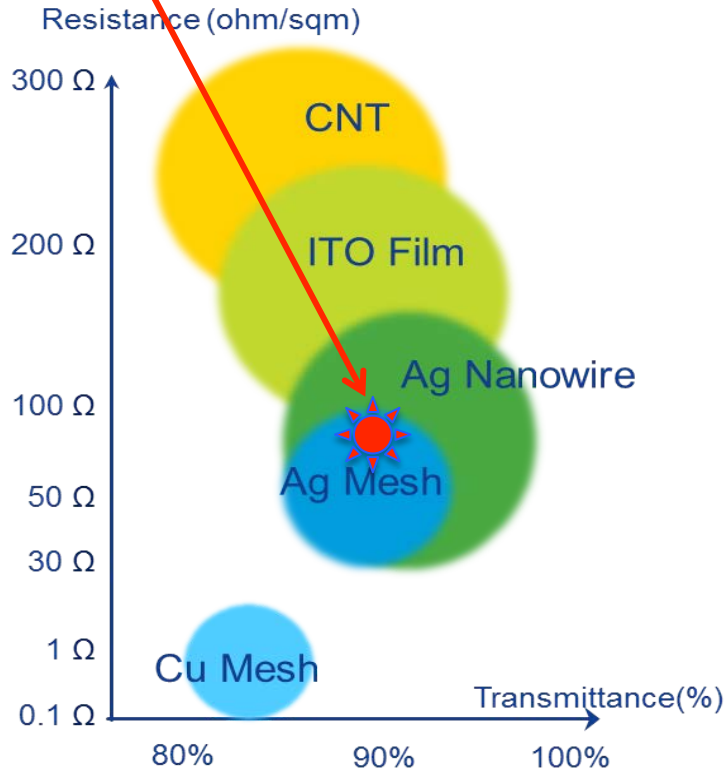
Capacitive Touch sensor stack with ITO – 2 ITO layers + 14 other layers



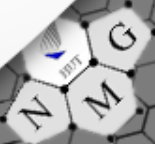
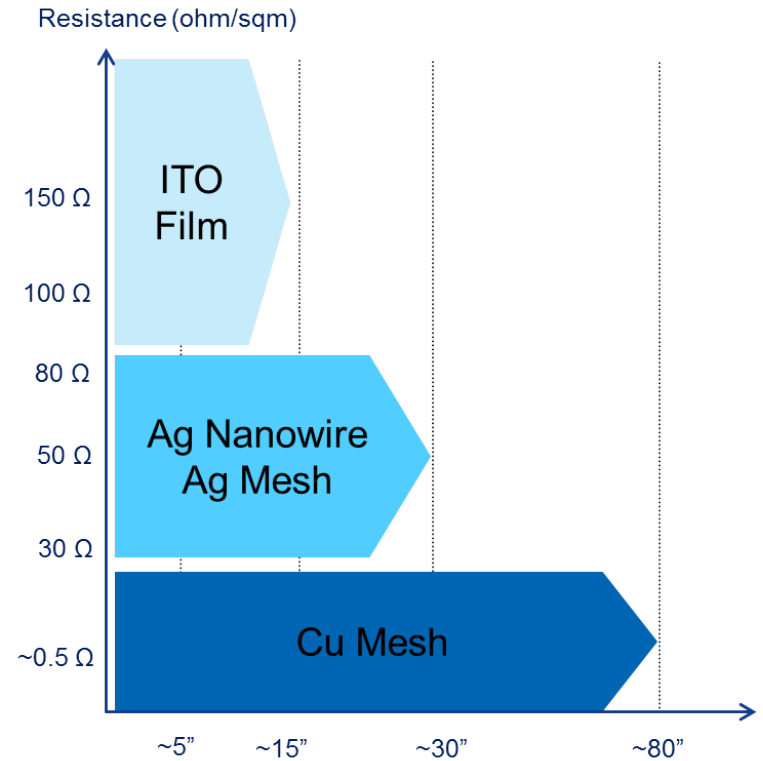
Emerging materials: metal mesh and nanowires, conducting polymers, CNT, graphene

Aalto Univ./ Canatu CNT film: below 100 ohm/sq @ 90 % T

Transparent conductive film comparison: Resistance and transmittance

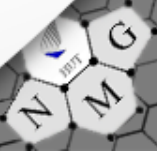


Transparent conductive film comparison: Resistance and screen size



Metal-based transparent conductive film types – Overall

	Ag Nanowire	Ag Halide	Cu Mesh	Ag (Direct Printing)	ITO
Resistance(Ω)	30~50 Ω	60 Ω	0.1~0.5 Ω	60 Ω	80 Ω or higher
Transmittance(%)	More than 90%	89% ~ 91%	≈ 85%	More than 90%	89% (Based on 150 Ω)
Merit	Able to use existing touch panel production lines	Micro patterning Double side patterning	Strong against static electricity Able to use existing PDP mesh infrastructure	Bezel wiring can be formed at once	Superior pattern visibility Proven for mass production Secured ample capacity
Demerit	Limited makers, milky color, weak chemical resistance	Moiré Limited width in production lines	Moiré, corrosion	Moiré, haze	Instability in indium supply
Flexibility	Good	Good	Good	Good	Bad
Method of securing pattern visibility	Partial etching, half etching	Partial etching, half etching	Introduce blackened layer	Process separate layer that controls light reflection	Introduce index matching layer
Layer Type	GFF / GF	GF2	GFF / GF	GFF / GF	GFF / GF / GF2
Price (ITO sensor: 1)	x1.2	x0.8~1	x0.8~1	x1	x1
Target Application	Large laptop~AIO PC	Smartphone~AIO PC	Large laptop~electronic board	Large laptop~AIO PC	Smartphone~laptop
Major Supplier	LGE, E&H, Toray, Okura, Nitto, Hyosung, Cheil Industry, Ijin Display, O-film, Carestream	Fujifilm, Mitsubishi Paper, Kodak	LG Chem, Toppan, DNP, Toray, Atmel, Panasonic, Fujikura	Mirae Nanotech, O-film, LGI	Nitto, LG Chem, Oike, Sekisui, Gunze, MAX film, LG Hausys, Miraestech, O-film



Requirements to material and devices for flexible, transparent and stretchable electronics

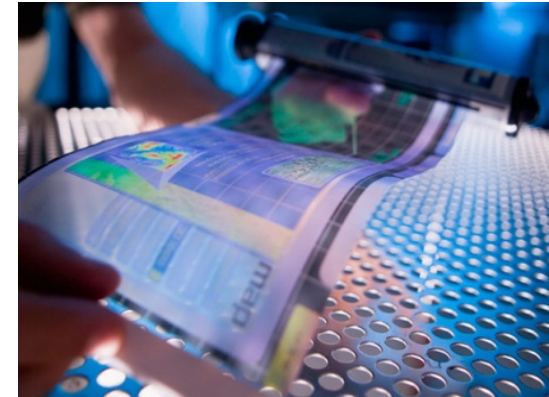
Silicon and ITO : Hard, Fragile → Plastic: Flexible, Elastic

Fabrication on plastic substrate

→ Low temperature process

Low-cost fabrication

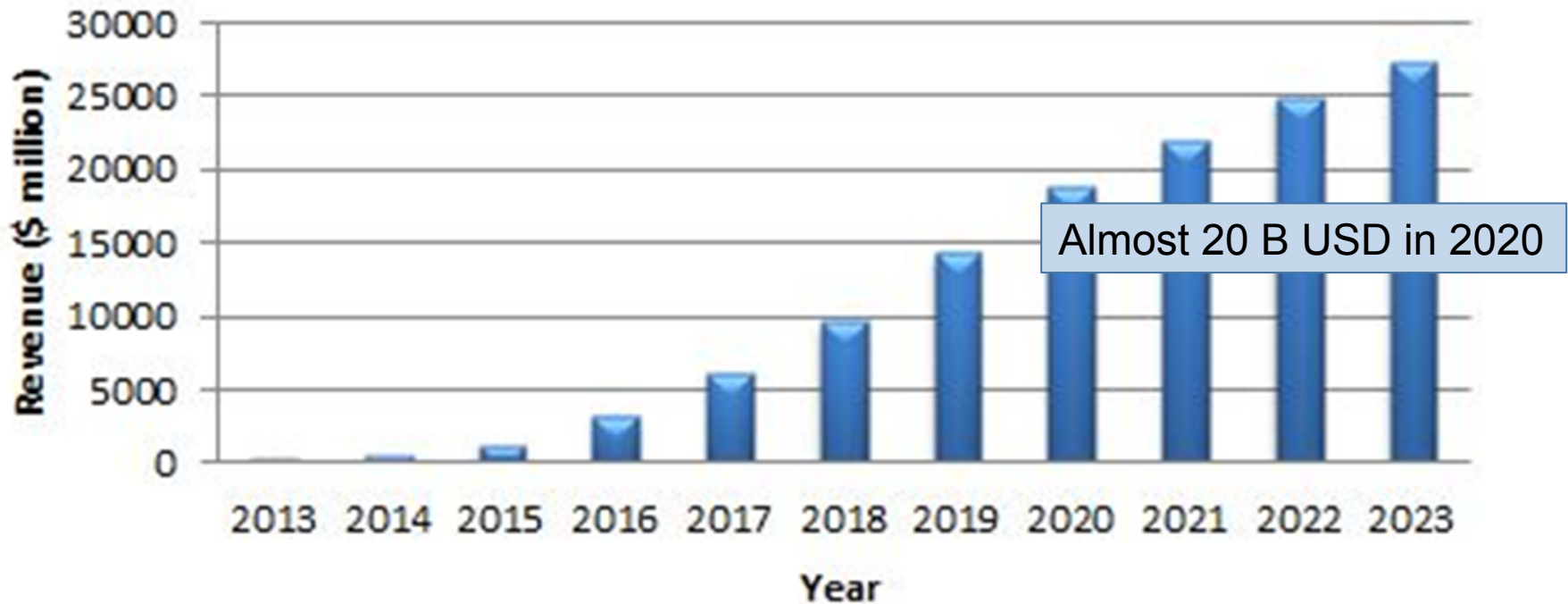
→ Atmospheric pressure process
High-speed printing method
Roll-to-roll manufacturization



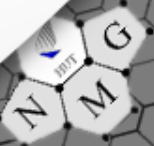
Hewlett-Packard

Deflection in the market 1:
Flexible Products Finally Coming of Age

**Flexible and curved display revenue
forecast (\$ million)**



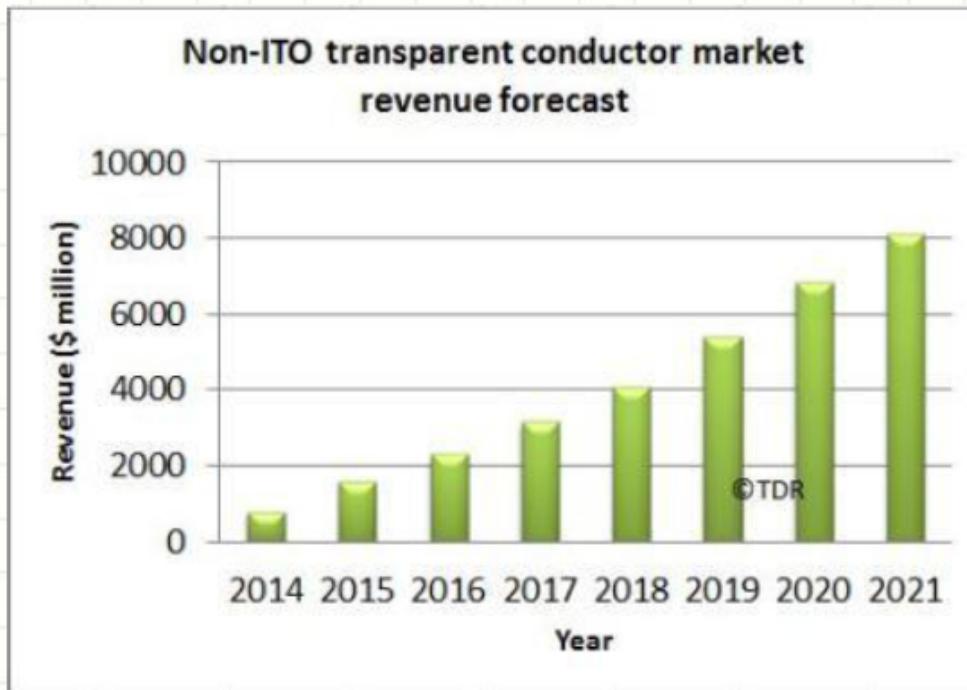
Source: Touch Display Research, Flexible and Curved Display Technologies and Market Forecast Report, September 2013



Deflection in the market 2:

ITO Replacements Finally Coming of Age

- Touch Display Research forecasts the non-ITO transparent conductor market will grow from \$206 million in 2013 to \$8 billion by 2021.



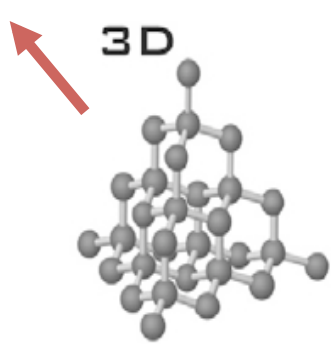
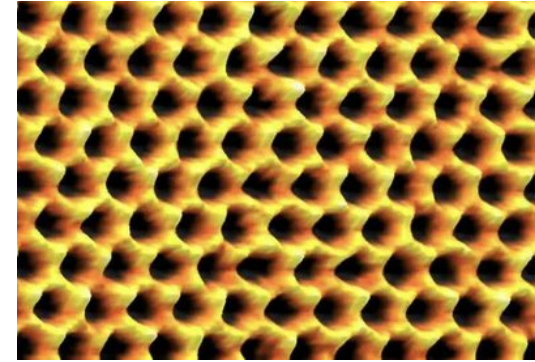
Source: Touch Display Research,
ITO-replacement report, Nov, 2014

Traditional thin film transistors materials

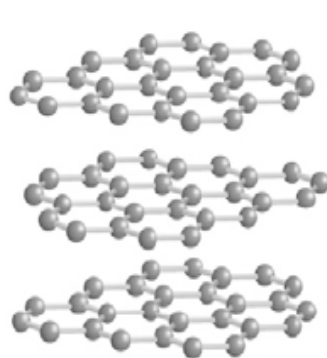
Material	Mobility (cm ² /Vs)	Method (Process temp.)	Flexibility	Large area	Cost	Stability
Poly-Si	30~300	Vac. CVD (500°C)	Bad	Fair	High	Very good
Amorphous-Si	0.5~1	Vac. CVD (> 200°C)	Bad	Fair	High	Very good
Oxide (InGaZnO)	1~10	Vac. Sputter (R.T.~200°C)	Good	Fair	Moderate	Very good
Organic	0.01~10	Solution, Sublimation (R.T.)	Good	Very good	Low	Bad

Additional important parameter: on/off ratio is larger than 1 000 000 = 10^6
 (needed for display and digital (IC) applications)
 Manufacturing yield very important for real applications

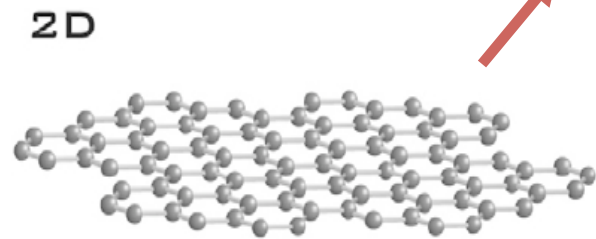
Allotropes of carbon – CNT and graphene - NOVEL NANOCARBONS for electronics ?



diamond



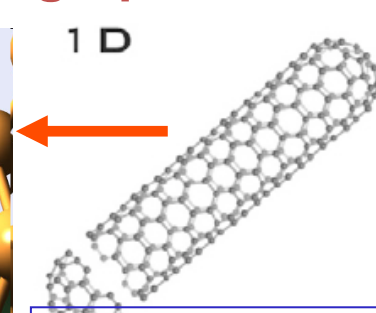
graphite



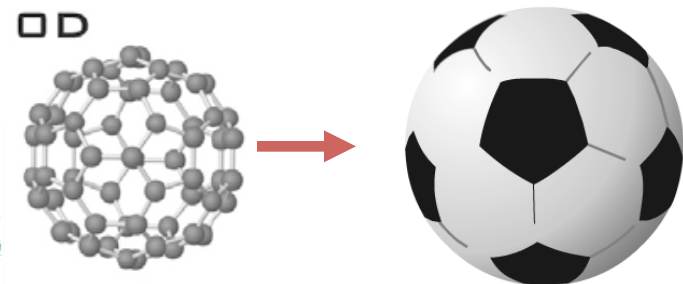
Graphene – NO band gap

C – C

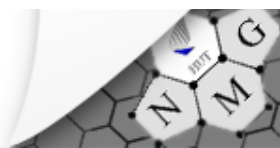
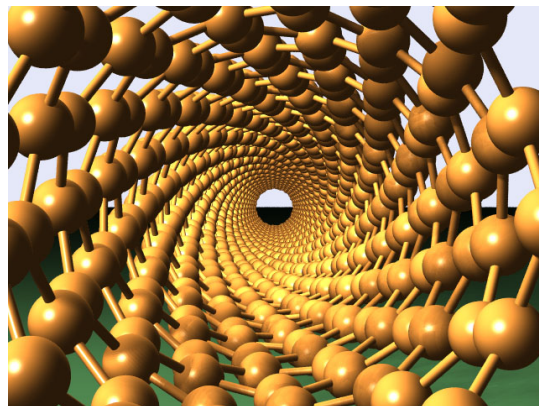
Nanobud (CNB)



Carbon nanotube – YES has band gap



fullerene

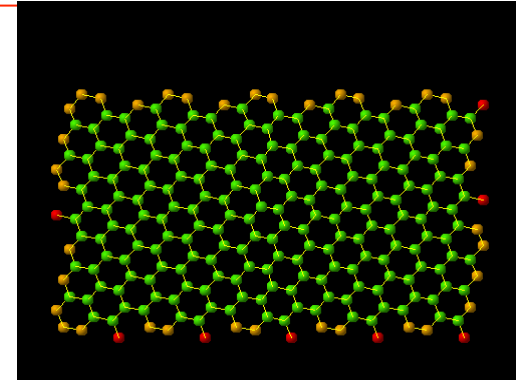
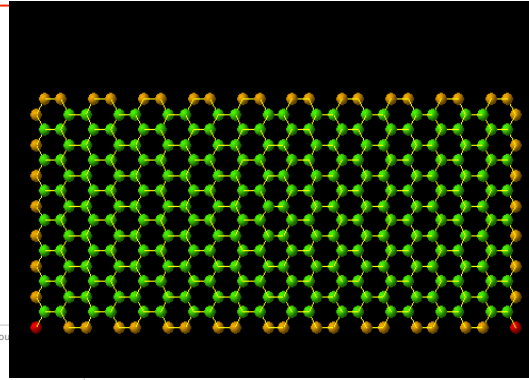
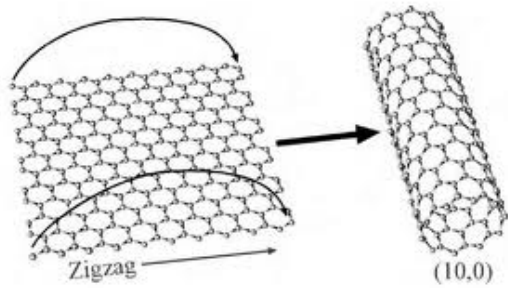


SWCNT and graphene show extremely high carrier mobility for flexible electronics applications = **fast large devices** -> ***Ideal material for printed electronics ?***

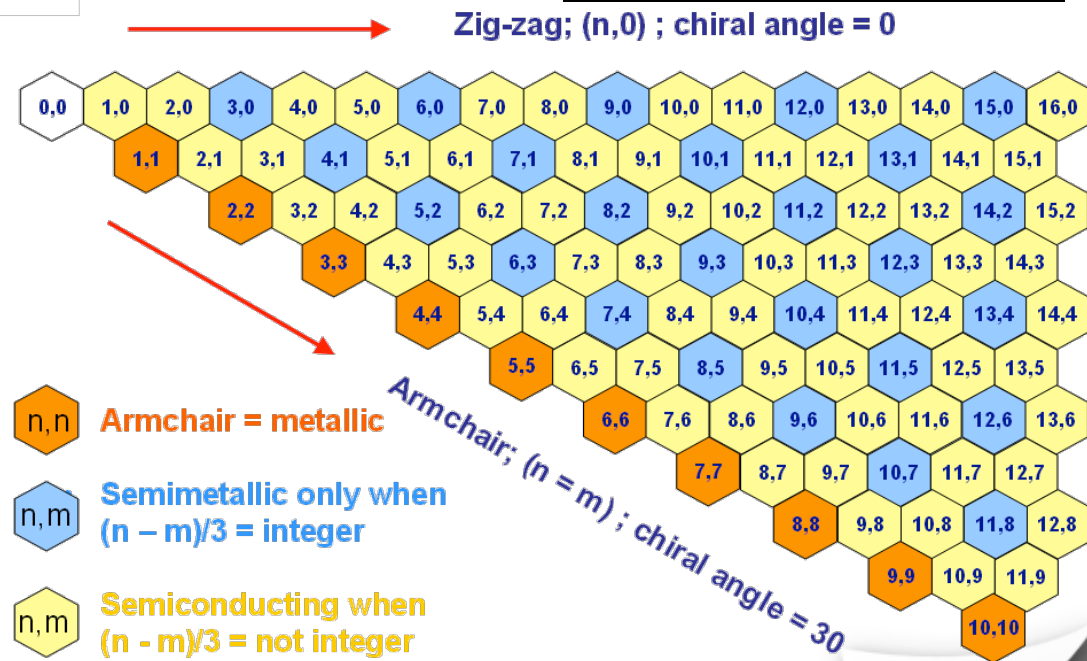
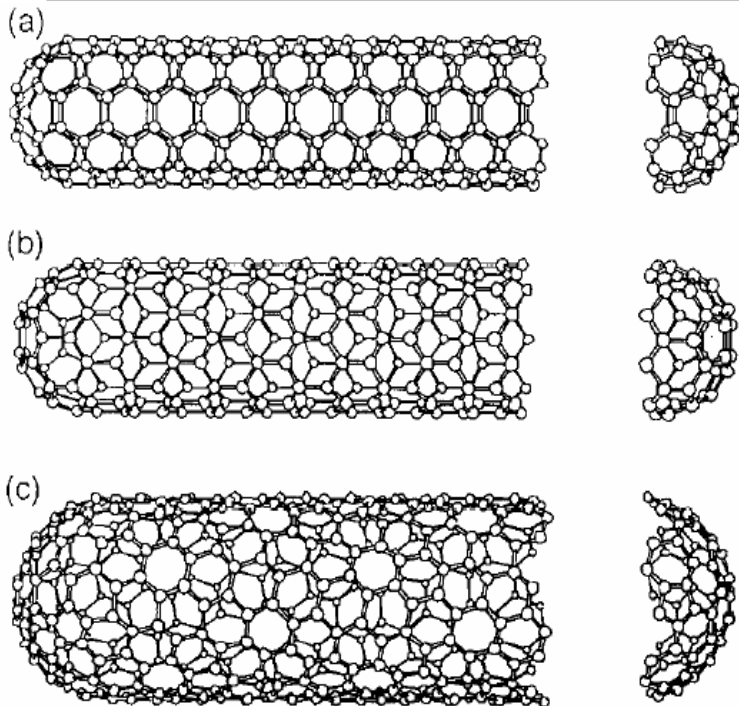
Material	Mobility (cm ² /Vs)	On/off ratio	Manuf. method (Process temp.)	Flexibility	Cost	Stability
Individual SWCNT on the substrate	10 000 – 200 000	10 ⁸	CVD (600-900°C)	Very good	High	Very good
SWCNT thin film on the substrate	5 - 2000	10 ⁴ - 10 ⁸	Depositon from solution or gas phase (ambient)	Very good	Low	Very good
Free-standing graphene single crystal	100 000 - 1 000 000	2-100	Exfoliation (not an industrial manufacturing process)	Very good	Very High	Very good
Graphene thin film on the Si substrate	1 000 – 5 000	2-100	CVD (900-1050°C)	Very good	High	Very good

On/off ratio: For digital electronics and display backplane >10⁶
New 2-D materials –lower mobility, on-off OK, high cost

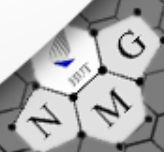
SWNT challenge is the material control: not only (n,m), but also *bundling, length, orientation*



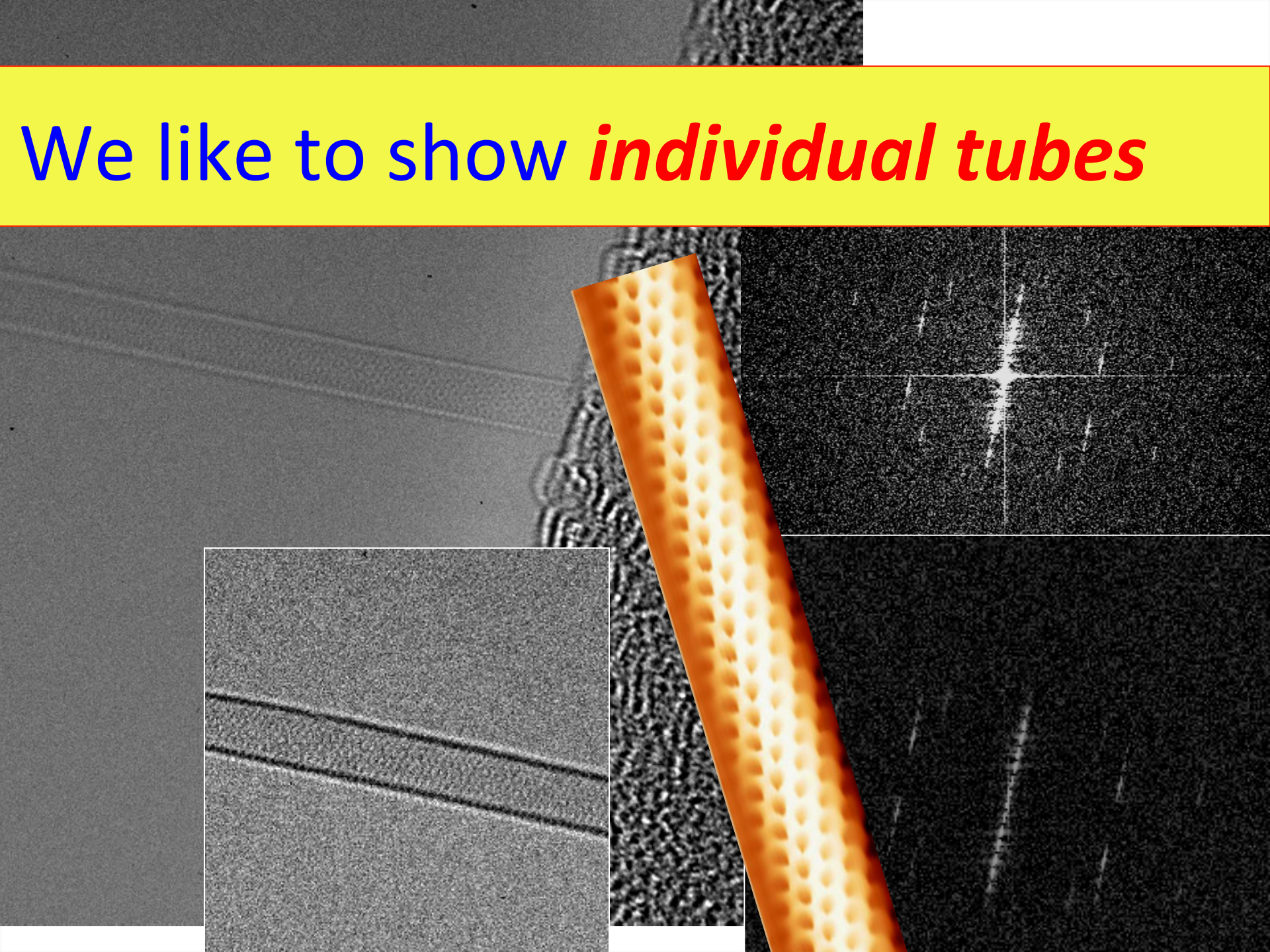
The image cannot be displayed. Your computer may not have enough memory to open the image, or the image may have been corrupted. Restart your computer, and then open the file again. If the red x still appears, you may have to delete the image and then insert it again.



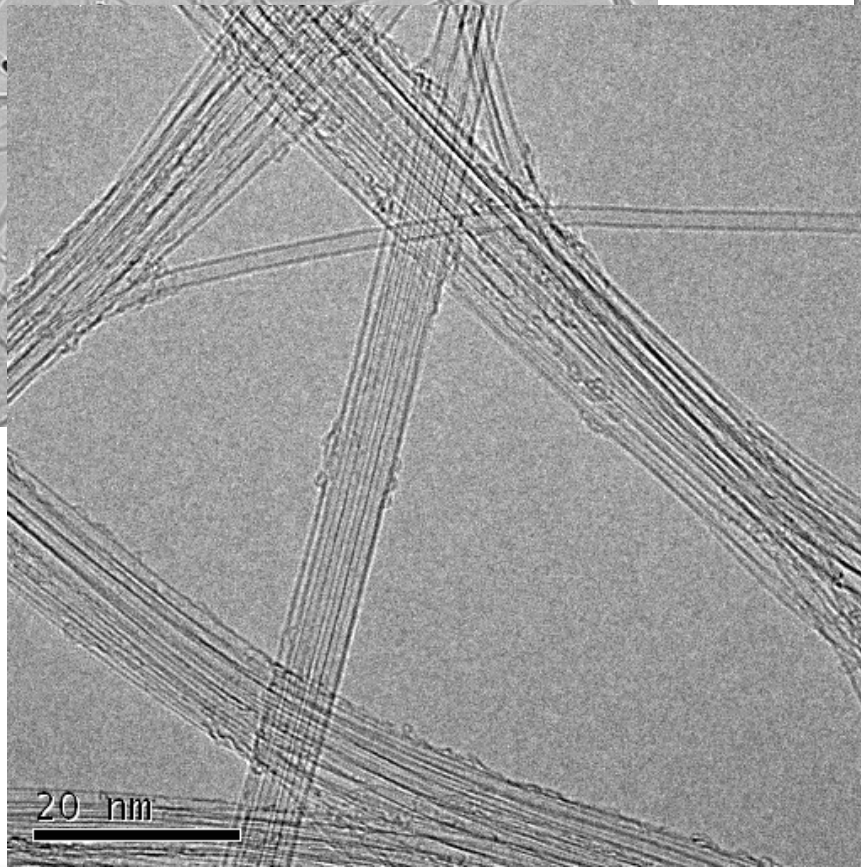
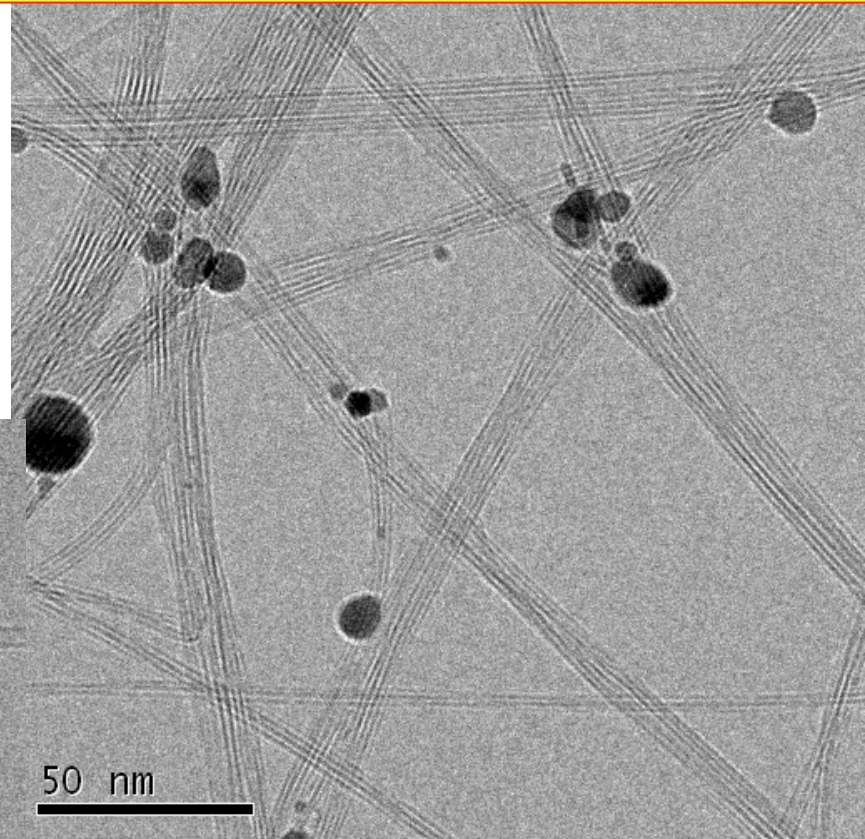
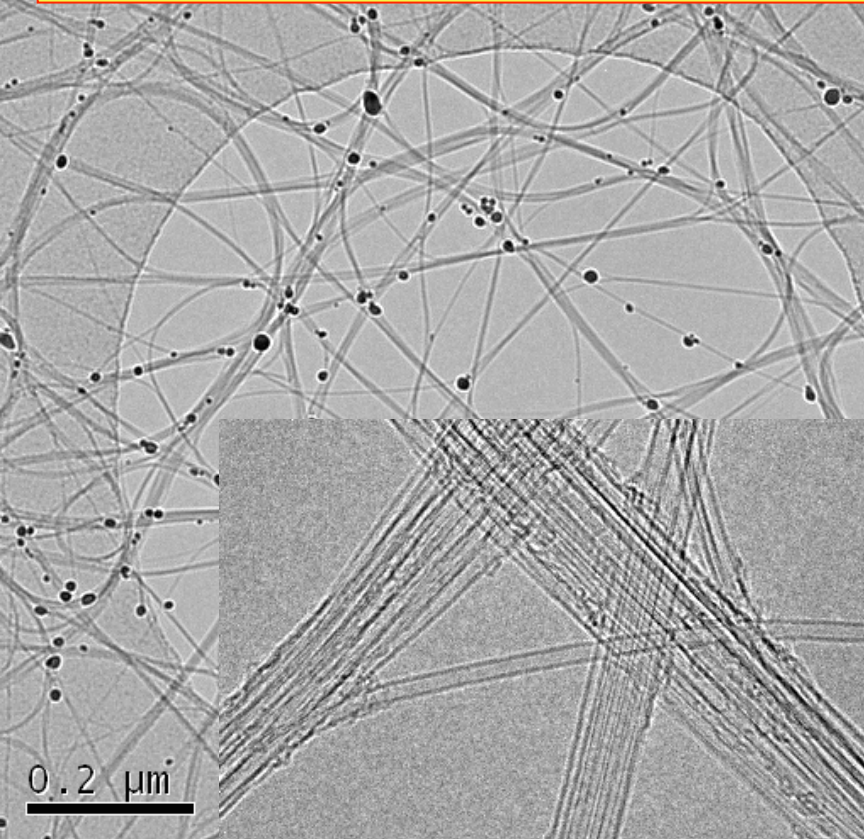
Rolling in different directions makes different kinds of tubes



We like to show *individual tubes*

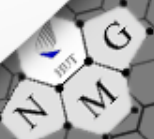


BUT mainly tubes are *in bundles*



Content

- **The need** to replace Indium and Gallium in transparent conductors (TCF) and transistor (TFT): carbon nanotubes as novel materials for flexible, transparent and stretchable electronics ?
- **Project objectives:** meet ITO (indium-tin oxide) and IGZO (indium-zinc-gallium oxide) specs with flexible SWNT thin films
- **Partners:** 3 from EU and 3 from Japan
- **Main results** for TCF, TFTs and solar cells
- **Future plans** – how to use the results



GOALS

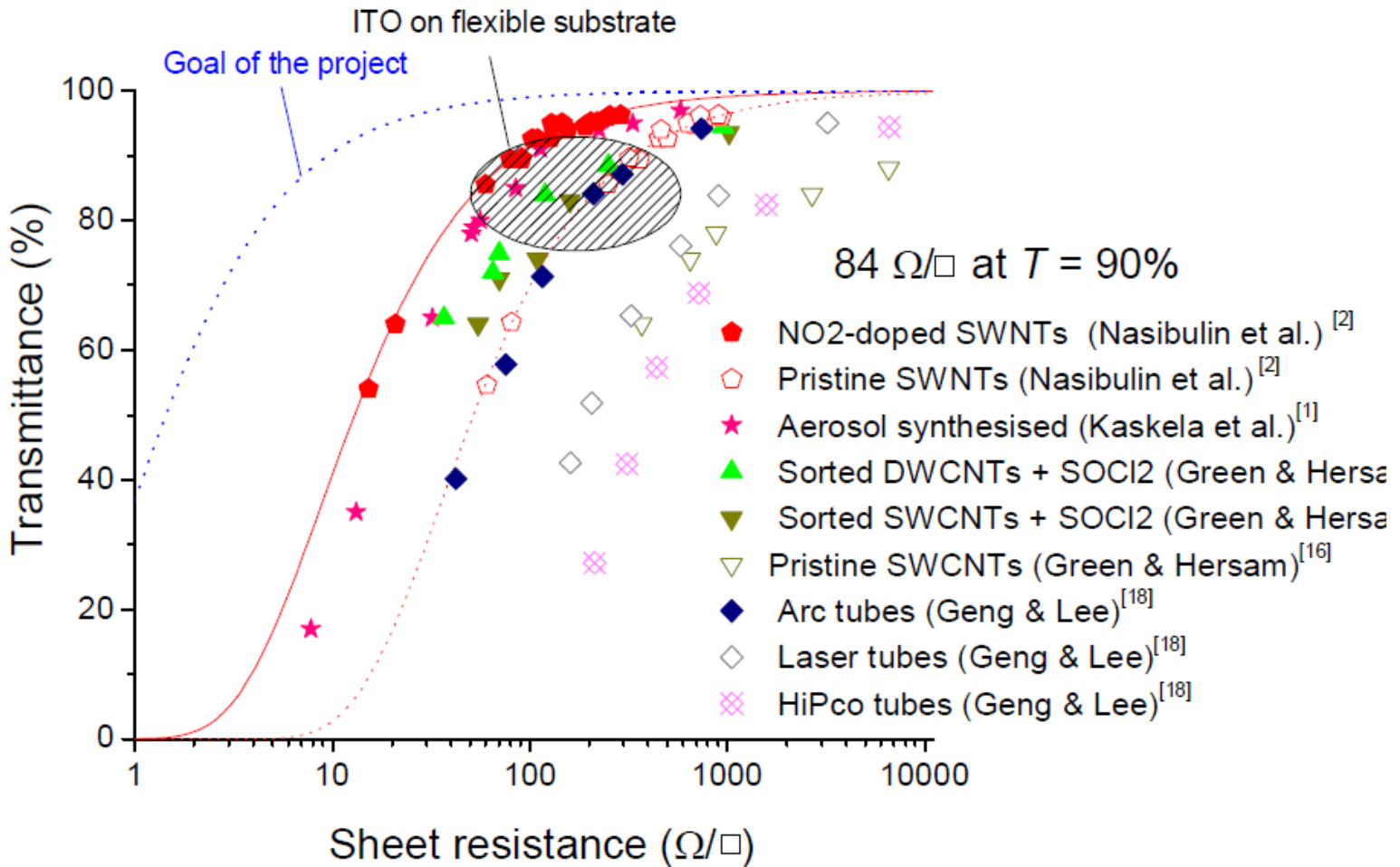


Fig. 3. Comparison of different transparent electrode materials: sheet resistance versus optical transmittance at 550 nm. The data produced by Aalto are shown by open and solid pentagons; the red lines show theoretical fits to our data; the blue line is for ITO on glass and the goal of the project.



GOALS

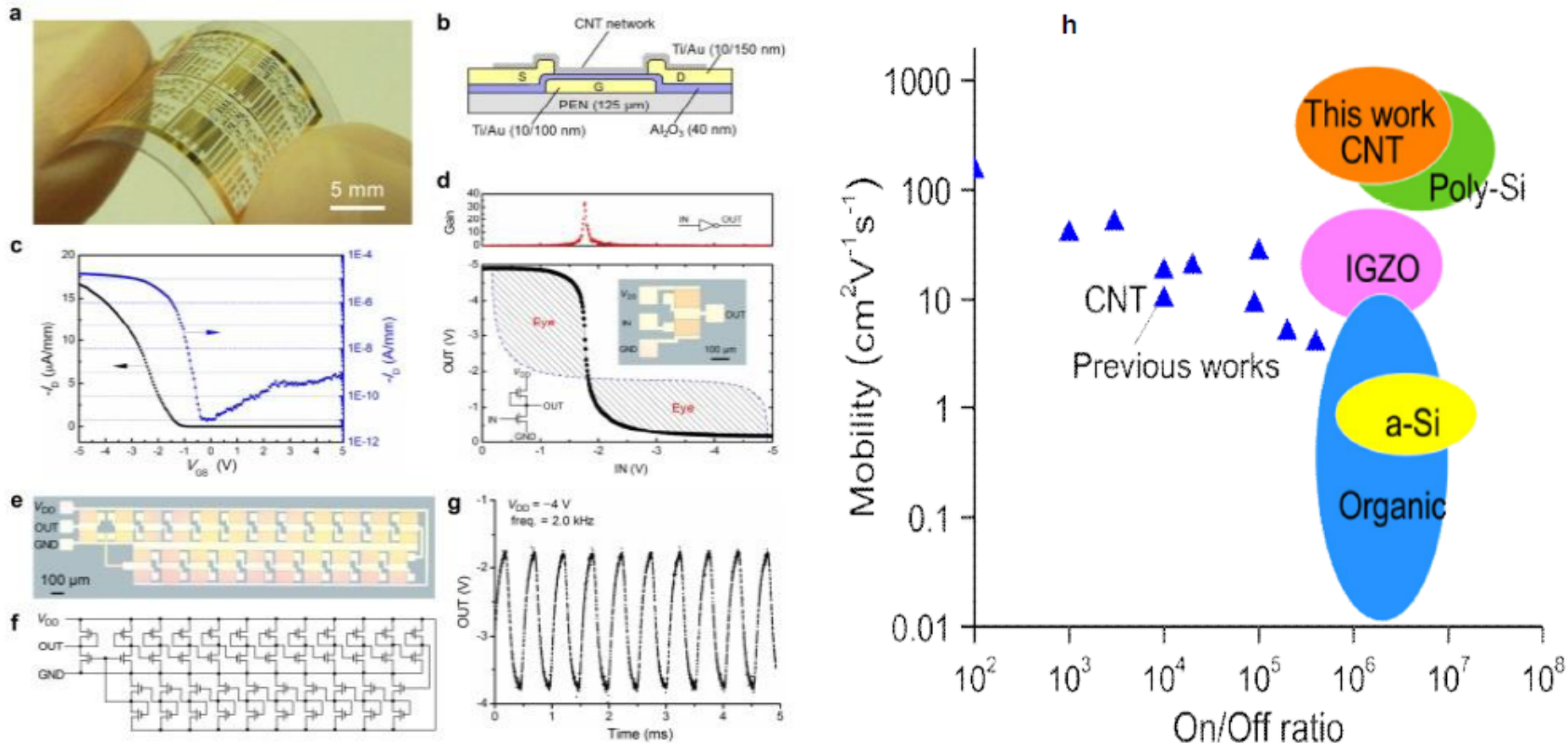


Fig. 4. SWCNT TFTs and ICs on flexible substrate. **a)** Photograph of fabricated devices on a flexible and transparent PEN substrate. **b)** Schematic cross section of a bottom gate TFT on PEN substrate with Al_2O_3 gate insulator. **c)** Transfer characteristics of a typical TFT with $L_c=100 \mu\text{m}$ at $V_{DS}=-0.5 \text{ V}$, $W_c=100 \mu\text{m}$. **d)** Input-output and gain characteristics of an inverter. Insets show the optical micrograph, circuit diagram and symbol of the inverter. **e, f)** Optical micrograph and circuit diagram of a 21-stage ring oscillator. **g)** Output characteristics of the ring oscillator with oscillation frequency of 2.0 kHz at $V_{DD}=-4 \text{ V}$. **h)** Mobility and on/off ratio. Comparison between our SWCNT TFTs with other representative TFTs based on SWCNT network^[6], amorphous-Si, polycrystalline Si, In-Ga-Zn-O semiconductors, and organic materials.

Provide Technology for Future Flexible, Bendable and Stretchable Devices

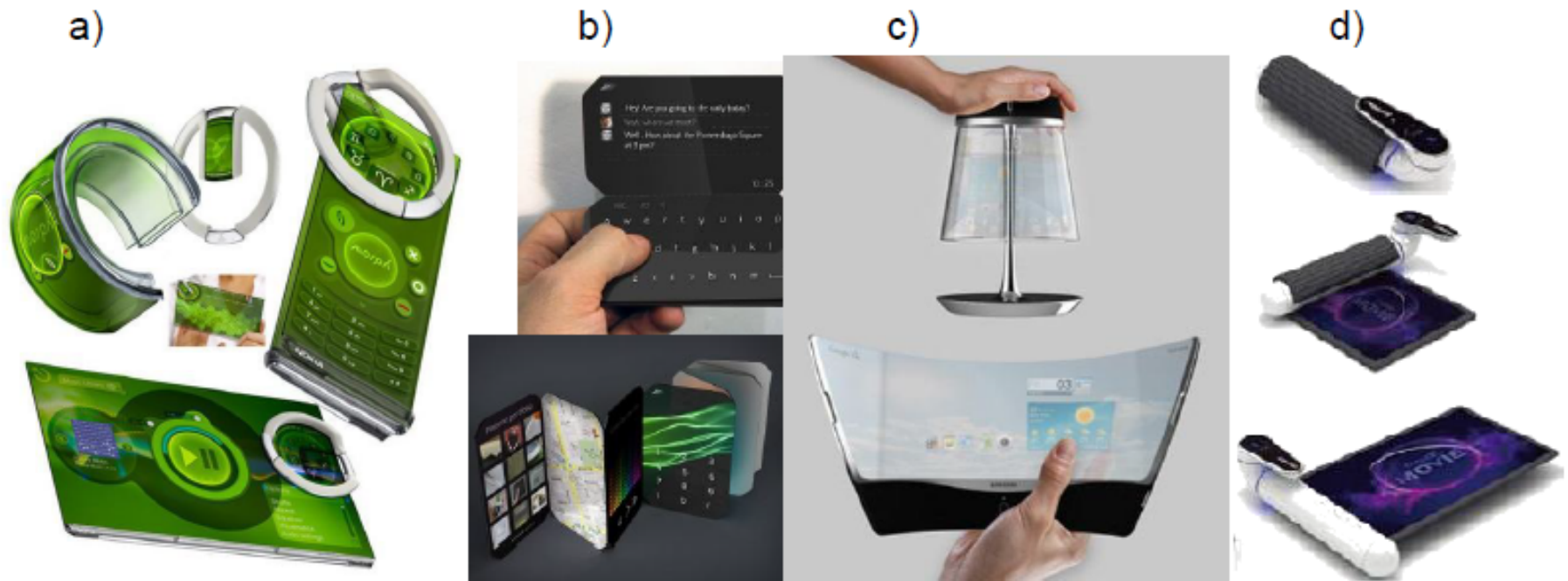
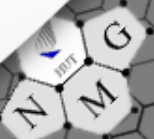


Fig. 1. A few examples of future concepts based on transparent, flexible and conductive materials: a) Nokia concept Morph; b) Smartphone Booklet Device; c) Curved Tablet Design - a flexible smartphone; d) Pen-sized rollup display. <http://www.concept-phones.com/?s=flexible>

Content

- **The need** to replace Indium and Gallium in transparent conductors (TCF) and transistor (TFT): carbon nanotubes as novel materials for flexible, transparent and stretchable electronics ?
- **Project objectives:** meet ITO (indium-tin oxide) and IGZO (indium-zinc-gallium oxide) specs with flexible SWNT thin films
- **Partners: 3 from EU and 3 from Japan**
- **Main results** for TCF, TFTs and solar cells
- **Future plans** – how to use the results





Co-funded by the European Union



Japan Science and Technology Agency

ONERA



東京大学 THE UNIVERSITY OF TOKYO



WP 1: Synthesis

Substrate CVD



S. Maruyama

Aerosol CVD



E. Kauppinen

<http://www.nt15.jp/>



Aalto University

WP 2: Formation mechanism

TEM observation



J. Wagner

Computational model



C. Bichara S. Maruyama

WP 3: SWCNT thin films

Fabrication



H. Shinohara

Transport mechanism



E. Kauppinen



Technical University of Denmark



WP 4: Device applications

Transistors



Y. Ohno

Touch sensors



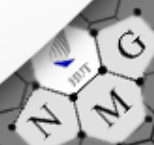
E. Kauppinen



NAGOYA UNIVERSITY



Aalto University



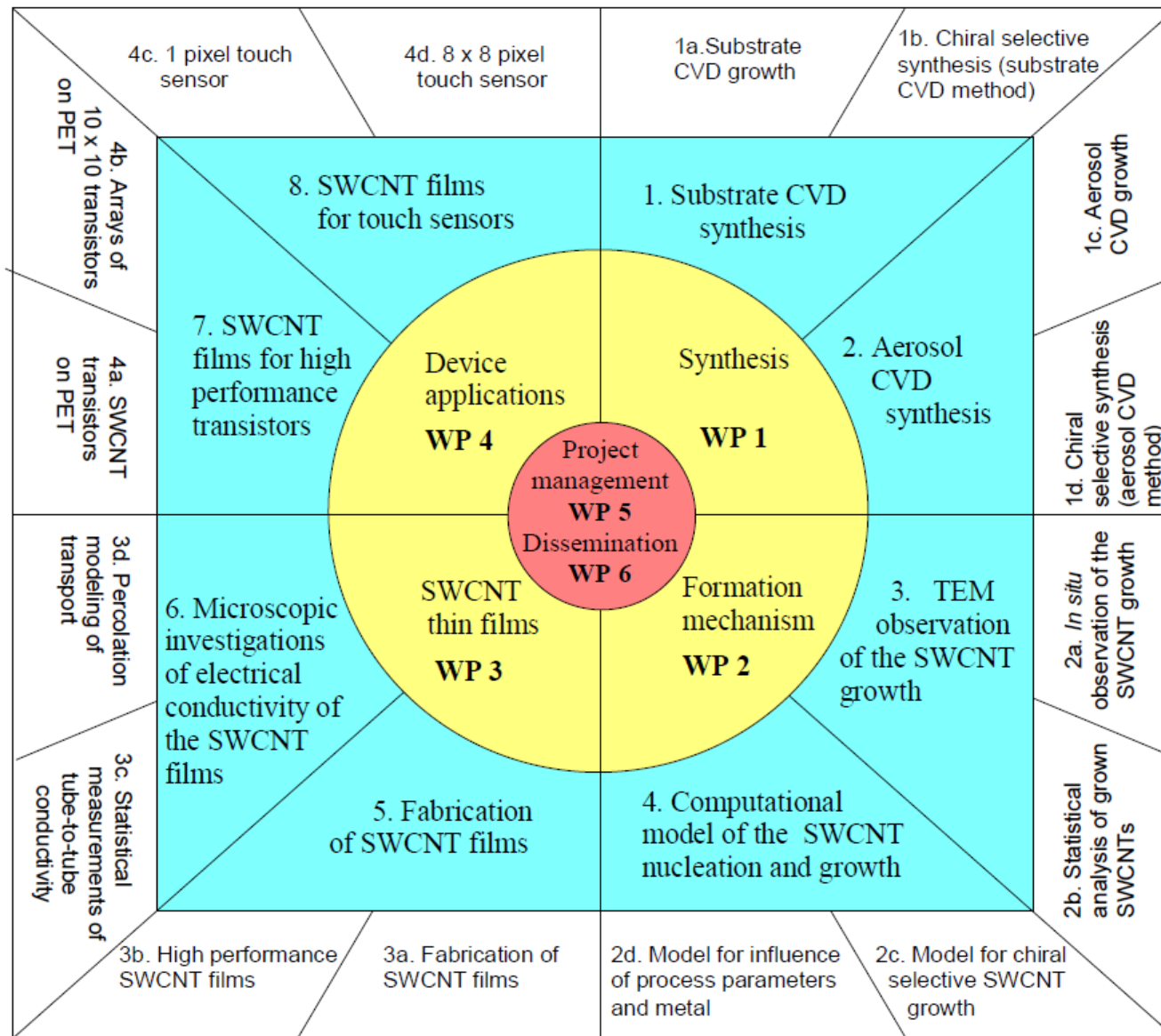
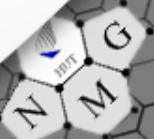


Fig.2. The structure of the project work packaged: 5 Work Packages (in the circle), 8 objectives around the Work Packages, divided into 16 subtasks. Subtasks of WP5 and WP6 are not shown. The illustration includes also the work carried out by the Japanese coordinated project.

Content

- **The need** to replace Indium and Gallium in transparent conductors (TCF) and transistor (TFT): carbon nanotubes as novel materials for flexible, transparent and stretchable electronics ?
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Aalto University novel dry, direct CNT film deposition method: *DPP* – *Direct Dry Printing*

Industrial manufacturing – Canatu Oy

Synthesis

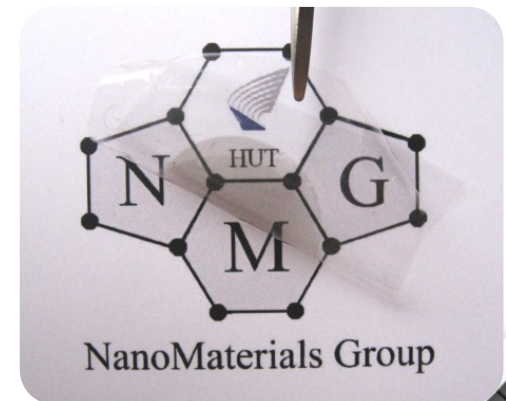
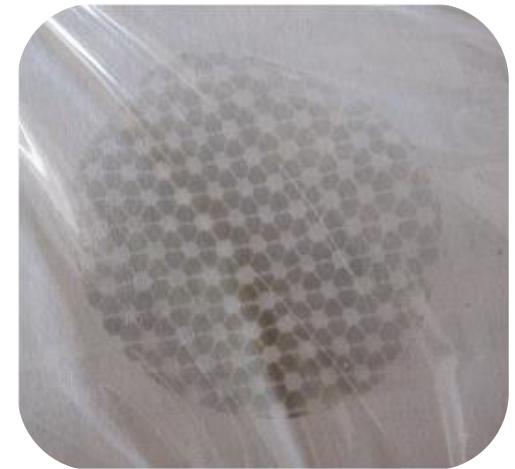
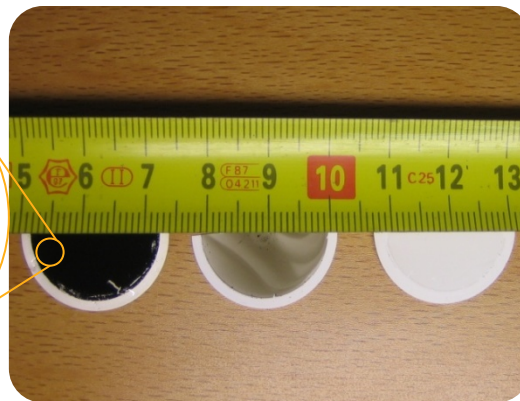
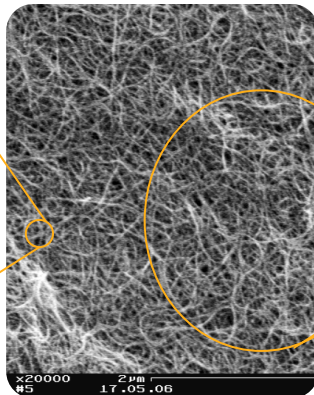
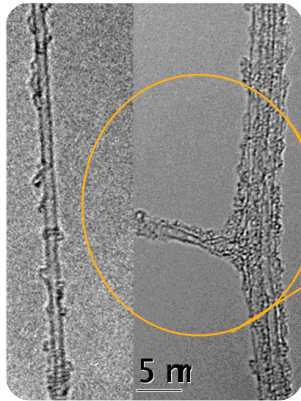
Deposition

Thin Films

SWCNTs in the reactor gas

Control of SWCNT properties

Patterned/non-patterned





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Heterojunction Solar Cell



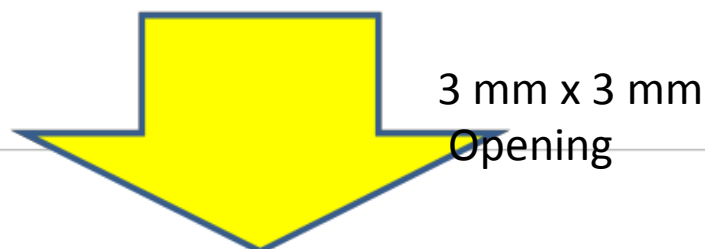
n-type Si ($7.5\text{-}12.5\ \Omega\text{cm}$, $\sim 10^{15}\ \text{cm}^{-3}$)

With $100\ \text{nm}\ \text{SiO}_2$

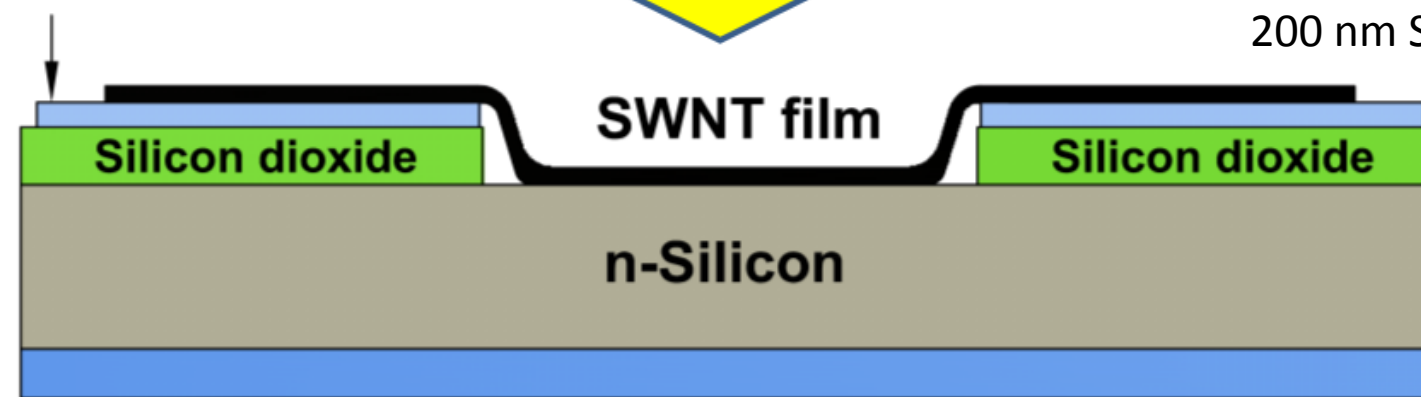
$5\ \text{M}\ \text{NaOH}$ at $90\ ^\circ\text{C}$ for 30min

RCA 2 Cleaning

$100\ \text{mW}/\text{cm}^2$ AM1.5G illumination



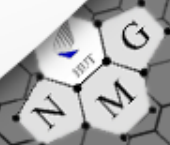
Pt electrode



200 nm SiO_2 , 100 nm Pt

Ti/Pt Rear contact

Ti 10 nm, Pt 50 nm

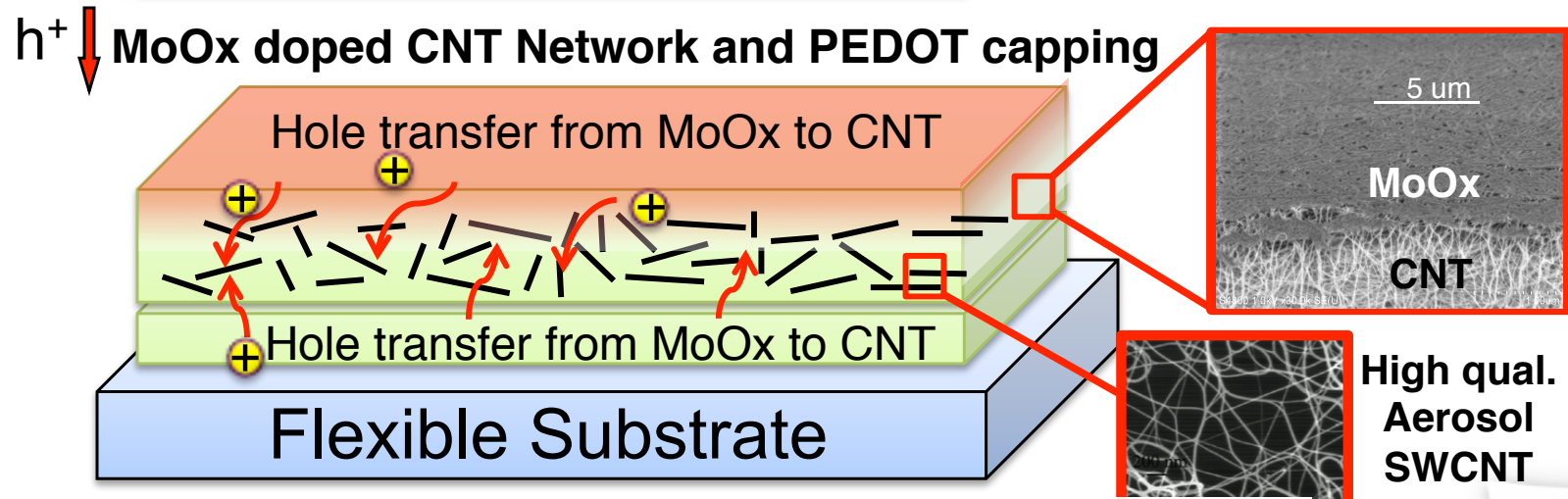
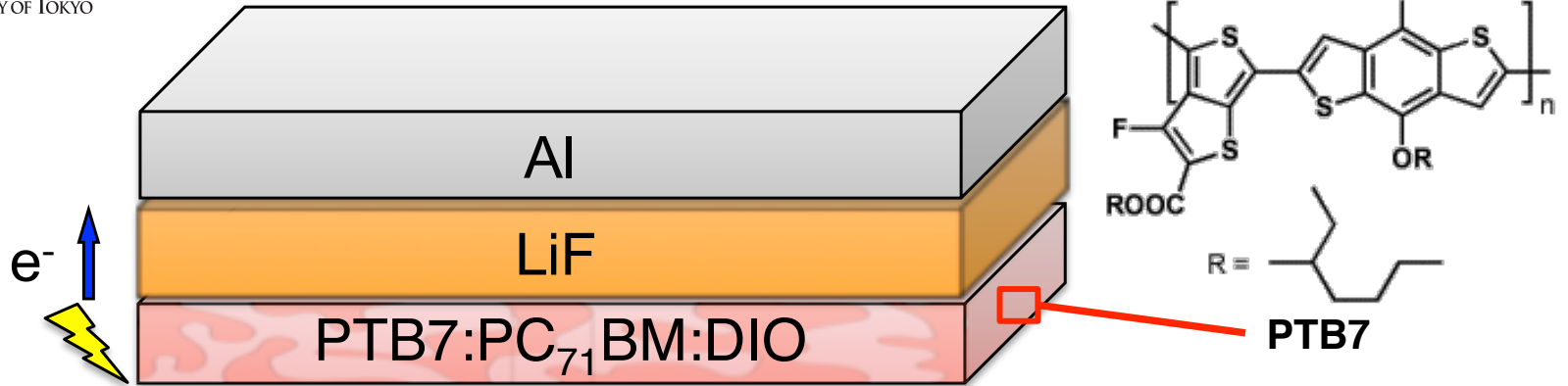




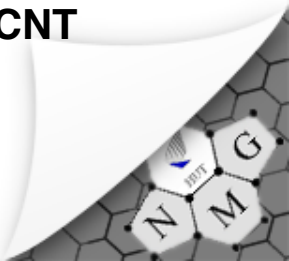
Organic Solar Cell



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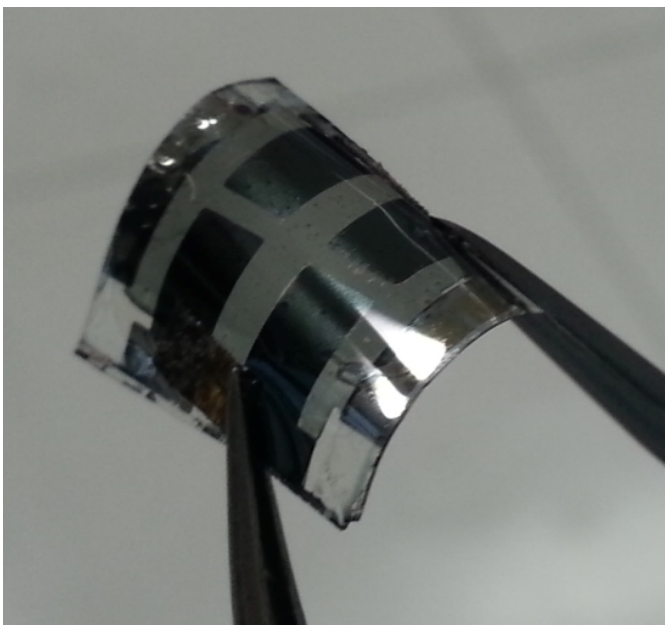
Il Jeon, K. Cui, T. Chiba, A. G. Nasibulin, E. Kauppinen, S. Maruyama, Y. Matsuo (2015)



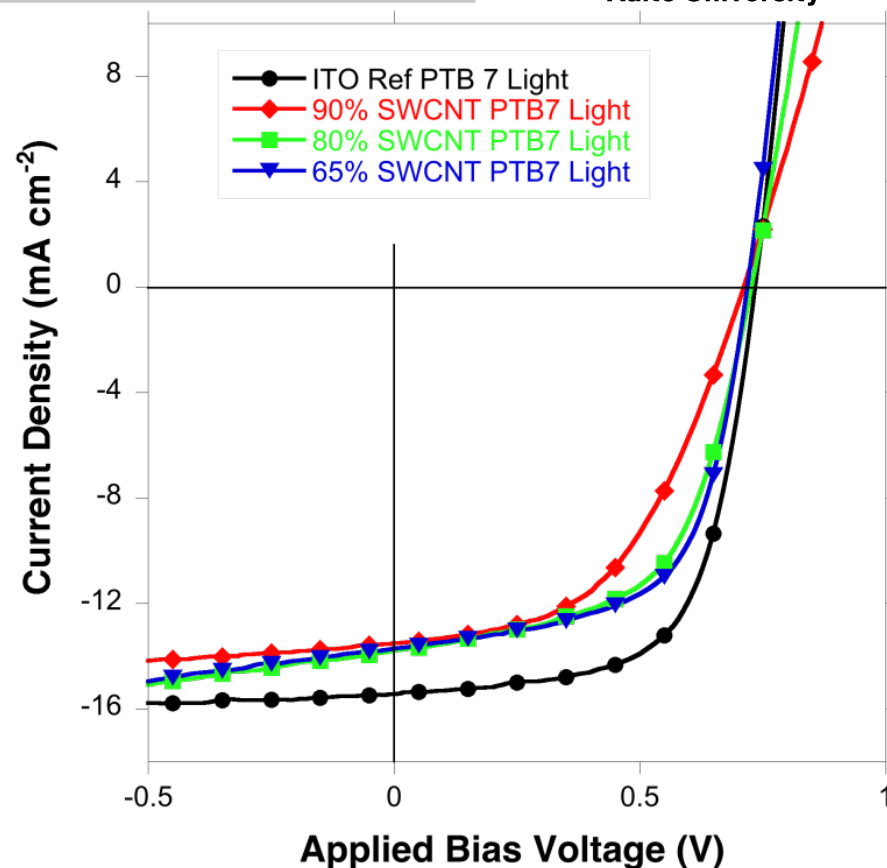


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Organic Solar Cell



Il Jeon, K. Cui, T. Chiba, A. G. Nasibulin, E. Kauppinen, S. Maruyama, Y. Matsuo (2015)



Anode	V_{oc} (V)	J_{sc} (mA/cm ²)	FF	R_s (Ω)	R_{sh} (Ω)	PCE (%)
ITO	0.74	15.45	0.64	92.0	2.85E+06	7.31
SWCNT 90%	0.71	13.51	0.50	137	7.46E+04	4.79
SWCNT 80%	0.73	13.79	0.57	116	9.77E+03	5.77
SWCNT 65%	0.72	13.72	0.61	51.6	1.22E+04	6.04

$$\text{Bundling} \propto N_{\text{CNT}}^2 \propto N_{\text{Cat}}^2$$

Schematics of formation mechanism during FC-CVD CO using Fe clusters

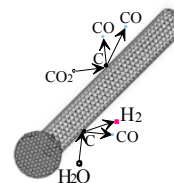
Nasibulin, Queipo, Shandakov, Brown, Jiang, Pikhitsa, Tolochko, Kauppinen, *J. Nanosci. Nanotech.*

6 1233.

Control :

- Diameter and length via temperature and oxidant (e.g. CO_2 , NH_3 , H_2O) concentration
- Bundling via catalyst concentration

908 °C



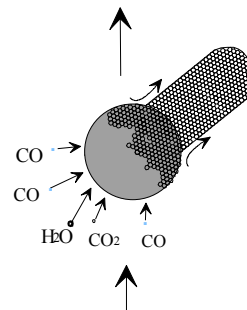
ethching reactions:



End of CNT growth

- CO DISPROPRTION AND CO HYDROGENATION REACTIONS ARE PROHIBITED ($t > 900 \text{ } ^\circ\text{C}$)

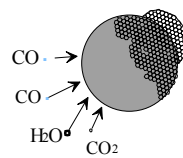
"growth window"



Steady-state growth of CNT

- C INCORPORATION INTO GRAPHENE LAYER
- REACTIONS OF CARBON RELEASE AND ETCHING: $2\text{CO} \rightleftharpoons \text{C} + \text{CO}_2$ AND $\text{H}_2 + \text{CO} \rightleftharpoons \text{C} + \text{H}_2\text{O}$

894 °C



Formation of graphene layer

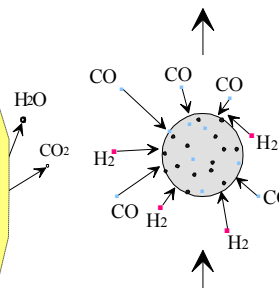
- HEXAGON AND PENTAGON FORMATION

CNT nucleation

- HEPTAGON FORMATION
- C INCORPORATION INTO GRAPHENE LAYER
- REACTIONS OF CARBON RELEASE AND ETCHING: $2\text{CO} \rightleftharpoons \text{C} + \text{CO}_2$ AND $\text{H}_2 + \text{CO} \rightleftharpoons \text{C} + \text{H}_2\text{O}$

700 °C

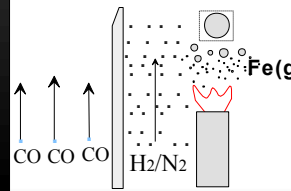
- REACTIONS ON REACTOR WALLS: $2\text{CO} = \text{C} + \text{CO}_2$ AND $\text{H}_2 + \text{CO} = \text{C} + \text{H}_2\text{O}$
- CO_2 and H_2O RELEASE



Particle saturation by C

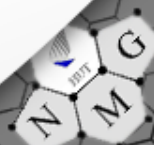
- REACTIONS: $2\text{CO} = \text{C} + \text{CO}_2$ AND $\text{H}_2 + \text{CO} = \text{C} + \text{H}_2\text{O}$
- C RELEASE ON SURFACE
- C DISSOLUTION

400 °C

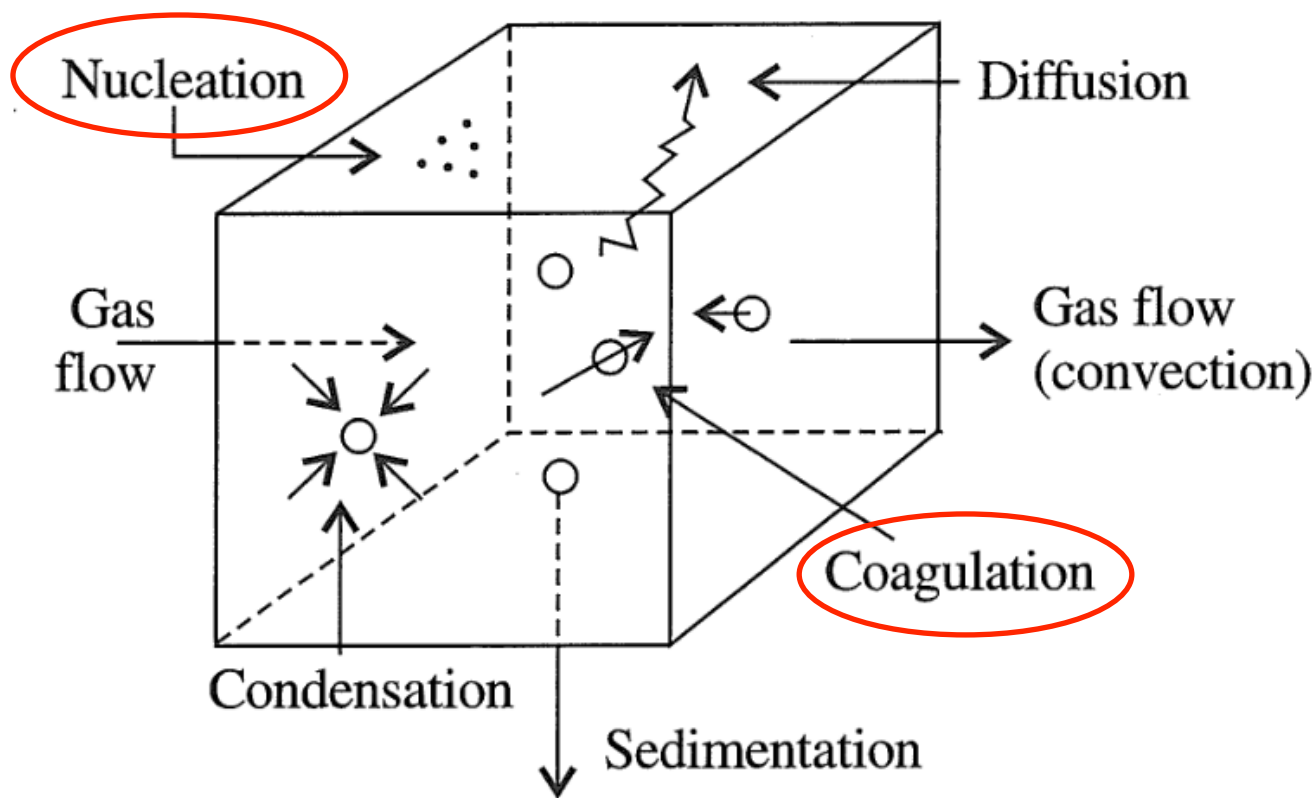


FE particle formation

- VAPOUR NUCLEATION
- CONDENSATION
- CLUSTER COAGULATION



Fundamentals of particles in gas dynamics – how catalyst particles and nanotubes behave during the floating catalyst CVD synthesis



Processes taking place in an elemental volume in the general dynamic equation. Gas flow produce particle transport across the element boundaries. In addition to gravitation, other force field can drive the fluxes, i.e. electrical potential, temperature gradient.

Basic dynamical processes in aerosol systems

Aerosol are physically unstable systems experiencing the continual influence of various dynamic processes. These processes change the aerosol properties, such as particle size and charge distribution, particle morphology, and so on. **N = number concentration in the FC-CVD gas**

General dynamics equations:

$$\frac{dN_k}{dt} = J(t)\delta_{i,k} + \frac{1}{2} \rho_g \sum_{j=1}^{k-1} \beta_{k-j,j} N_{k-j} N_j - \rho_g \beta_k N_k \sum_{j=1}^{\infty} N_j +$$

Nucleation
of Catalyst
particles

Collisions – catalyst particles and SWNTs

$$+ \rho_g \left(\beta'_{1,k-1} N'_1(t) N_{k-1} - \beta'_{1,k} N'_1(t) N_k \right)$$

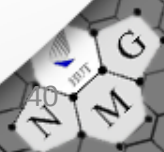
Condensation of catalyst metal vapour on SWNTs
and on non-active catalyst particles

β – the coagulation kernel (coefficient) if two colliding particles,

$\delta_{i,k}$ – Kroneker delta ($\delta_{i,k} = 1$ for $i=k$, $\delta_{i,k} = 0$ otherwise),

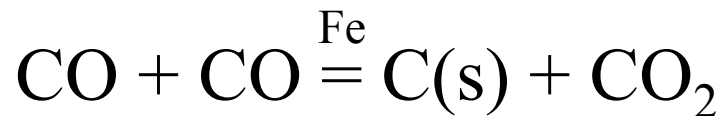
ρ_g – the carrier gas density, N'_1 - number concentration of condensing monomers.

β' – the collision frequency of monomers and particles,



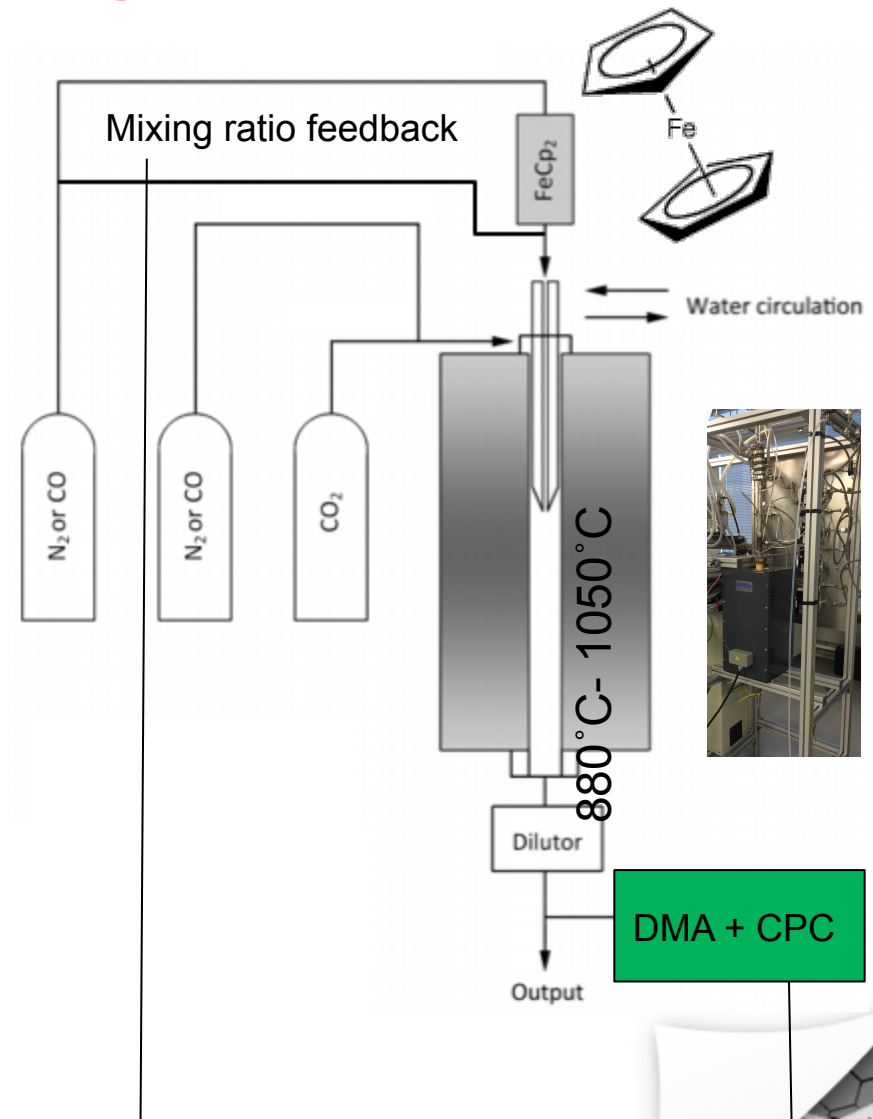
Catalyst concentration Controlled FC-CVD with Concentration Monitoring – New Reactor

- CO as carrier gas and carbon source with ferrocene and CO₂
- Particle formation by thermal decomposition of ferrocene
- SWCNTs grown in the gas flow via Boudouard reaction

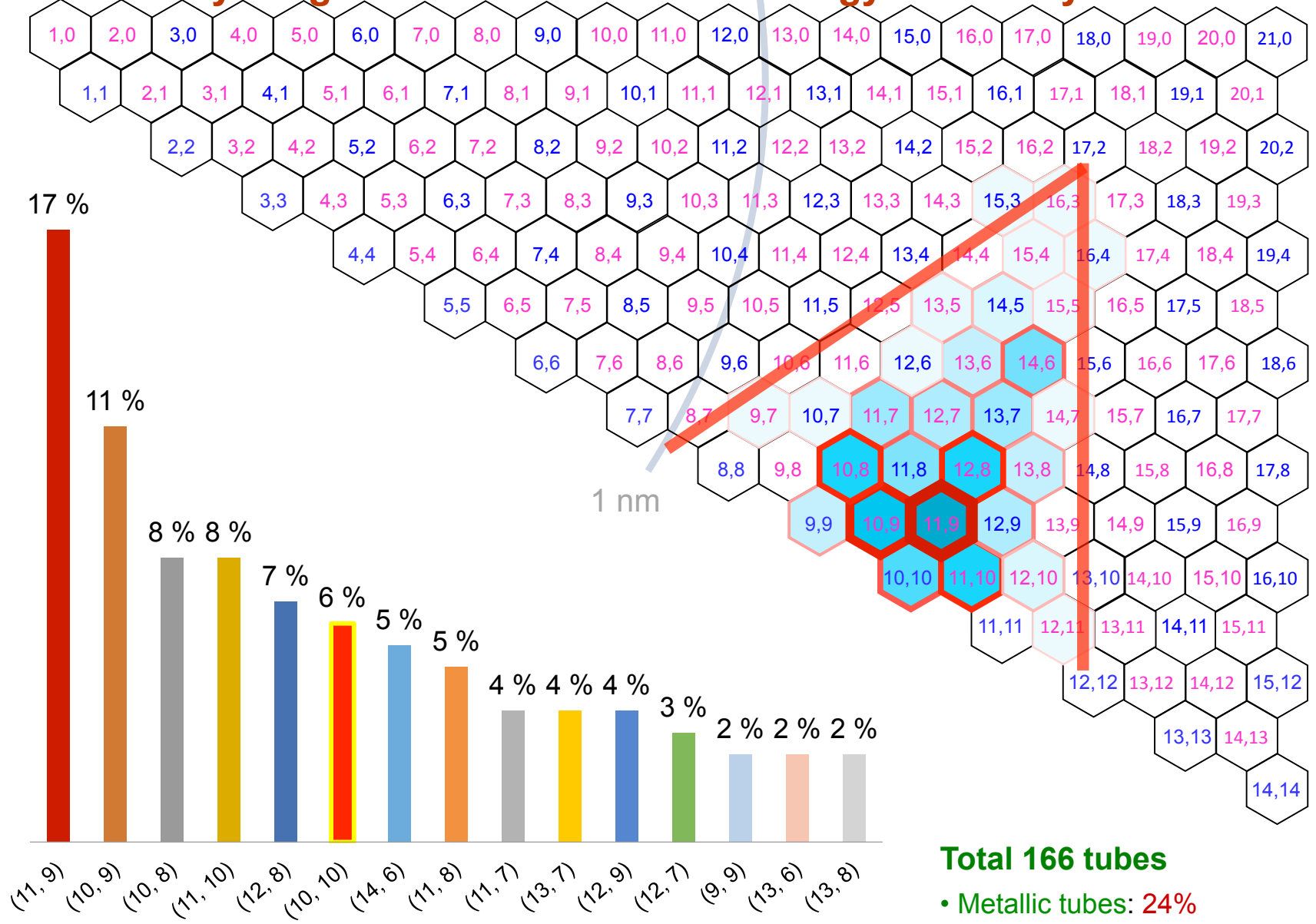


- Controlled concentration
 - 1e4 - 1e6 #/cm³
 - High individual SWCNT fraction
- Substantially improved
 - Stability
 - Performance

A. Kaskela et al. (2015) To be submitted



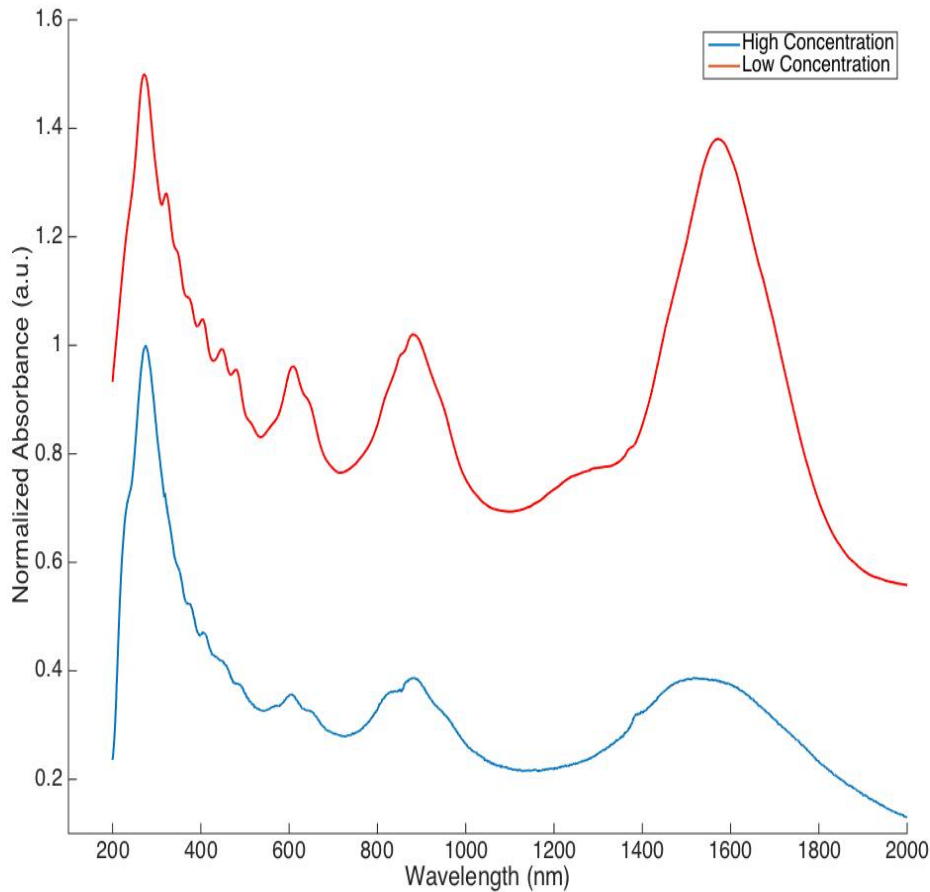
Aalto University 2nd generation FC-CVD technology– Fe catalyst and CO/CO₂



Note: Nanotubes with the occurrence rate less than 2% are not shown in the chart.

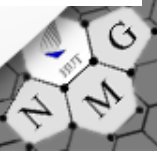
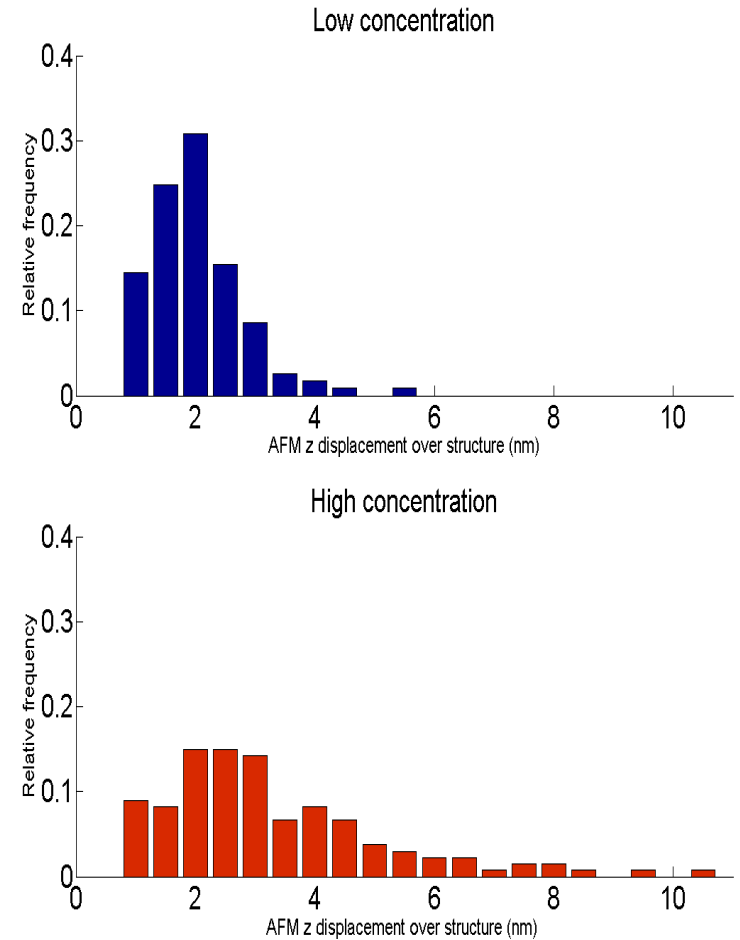
Jiang, H., Kaskela A. et al. (2015) In preparation

Optical Absorption Spectra of as-produced SWNT Thin Films



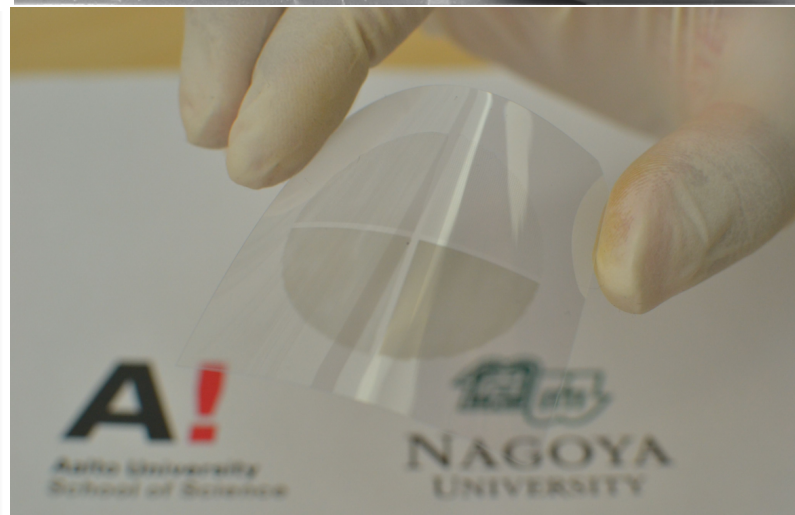
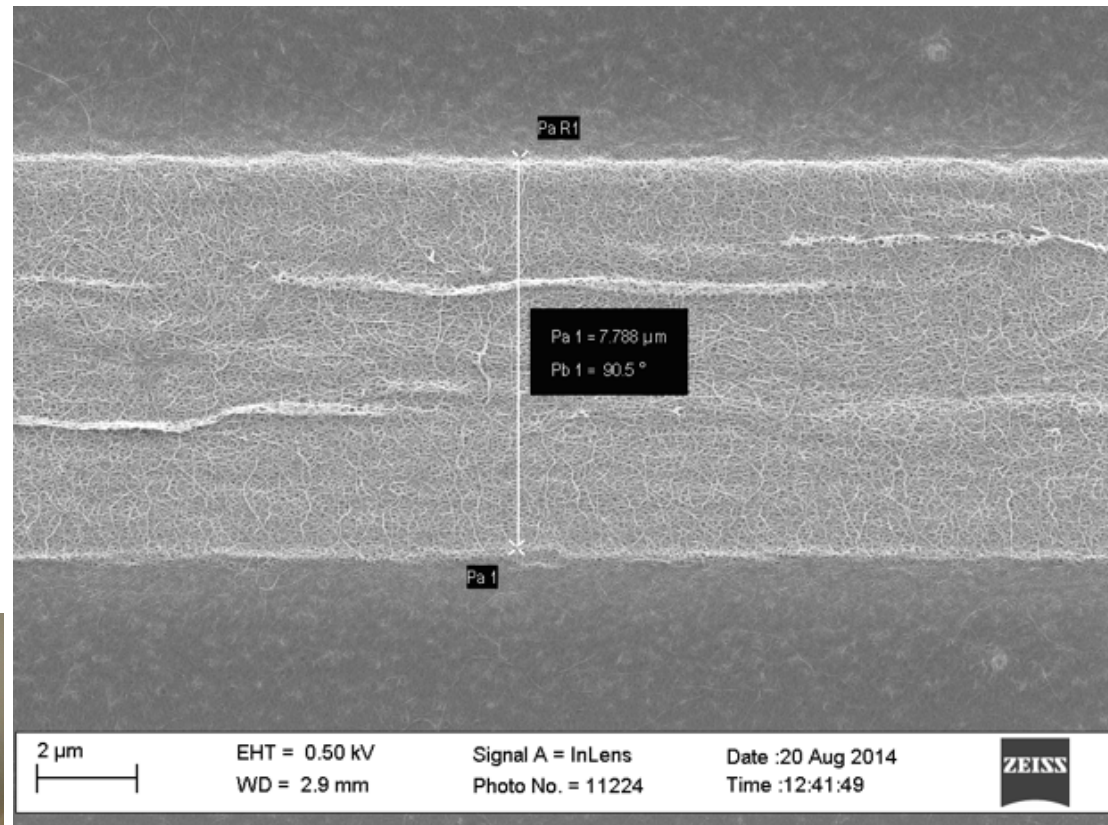
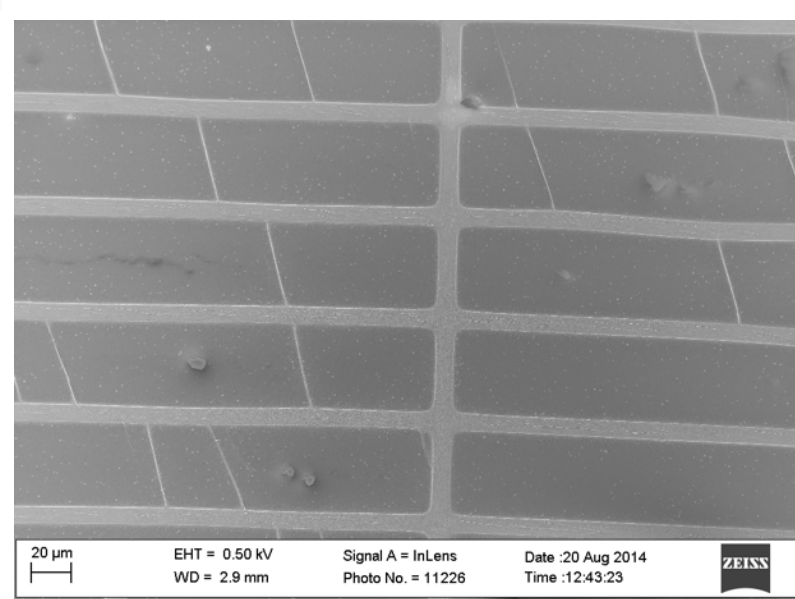
A. Kaskela, P. Laiho et al. (2015) To be submitted

Bundle Diameter Distribution from AFM

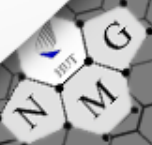


Micropatterned SWNT TCFs – 67 ohms/sq @ 97 % T

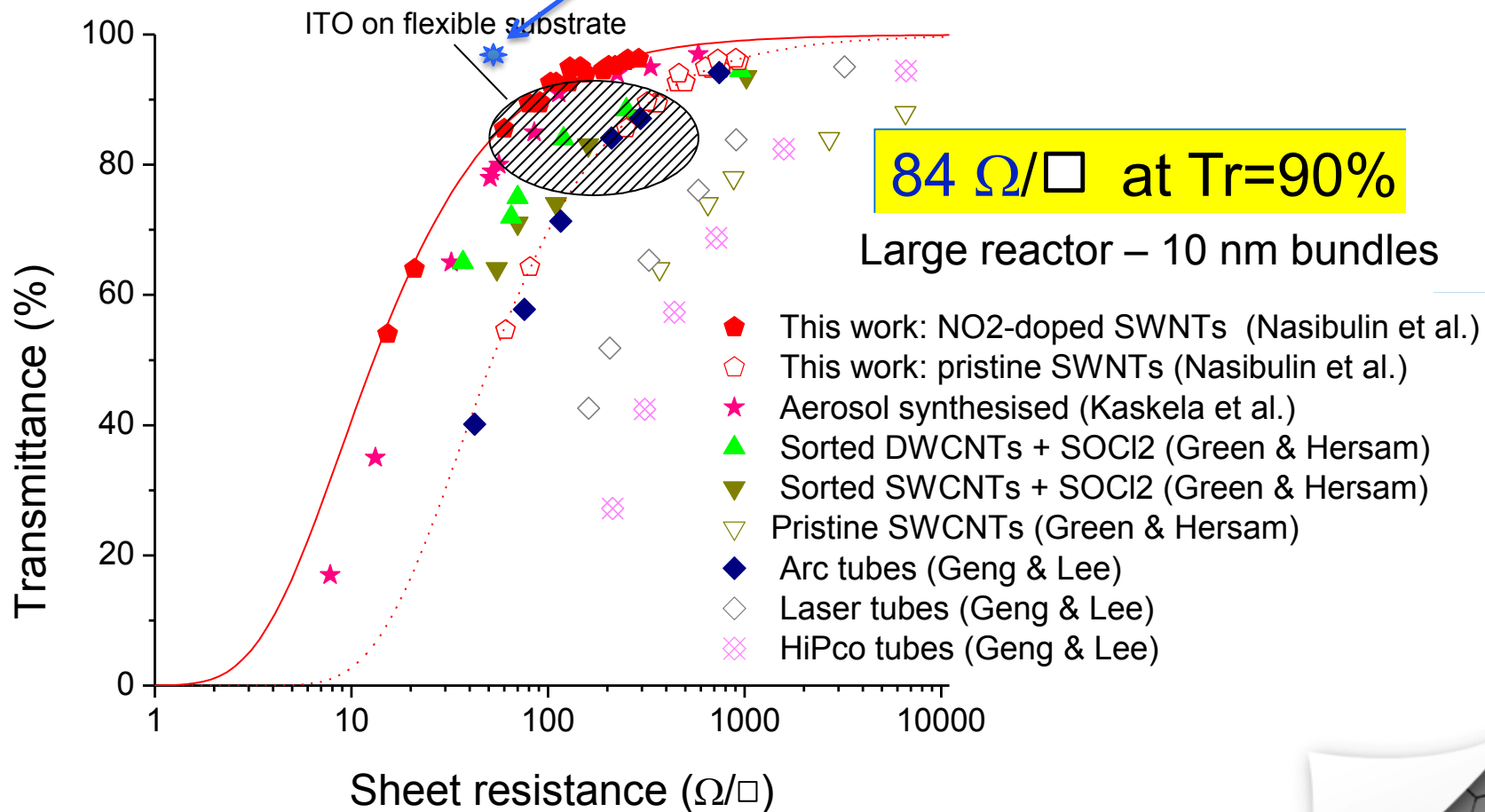
N. Fukaya, D. Y. Kim, S. Kishimoto, S. Noda, and Y. Ohno, "One-Step Sub-10 μm Patterning of Carbon-Nanotube Thin Films for Transparent Conductor Applications," ACS Nano, Apr. 2014.



A. Kaskela, Y. Ohno et al. (2015) To be submitted



With micropattern: 67 ohm/sq @ 97%T -
collaboration with Prof. Yutaka Ohno
Record performance level of SWCNT-based
transparent electrodes (1.7 nm tubes)

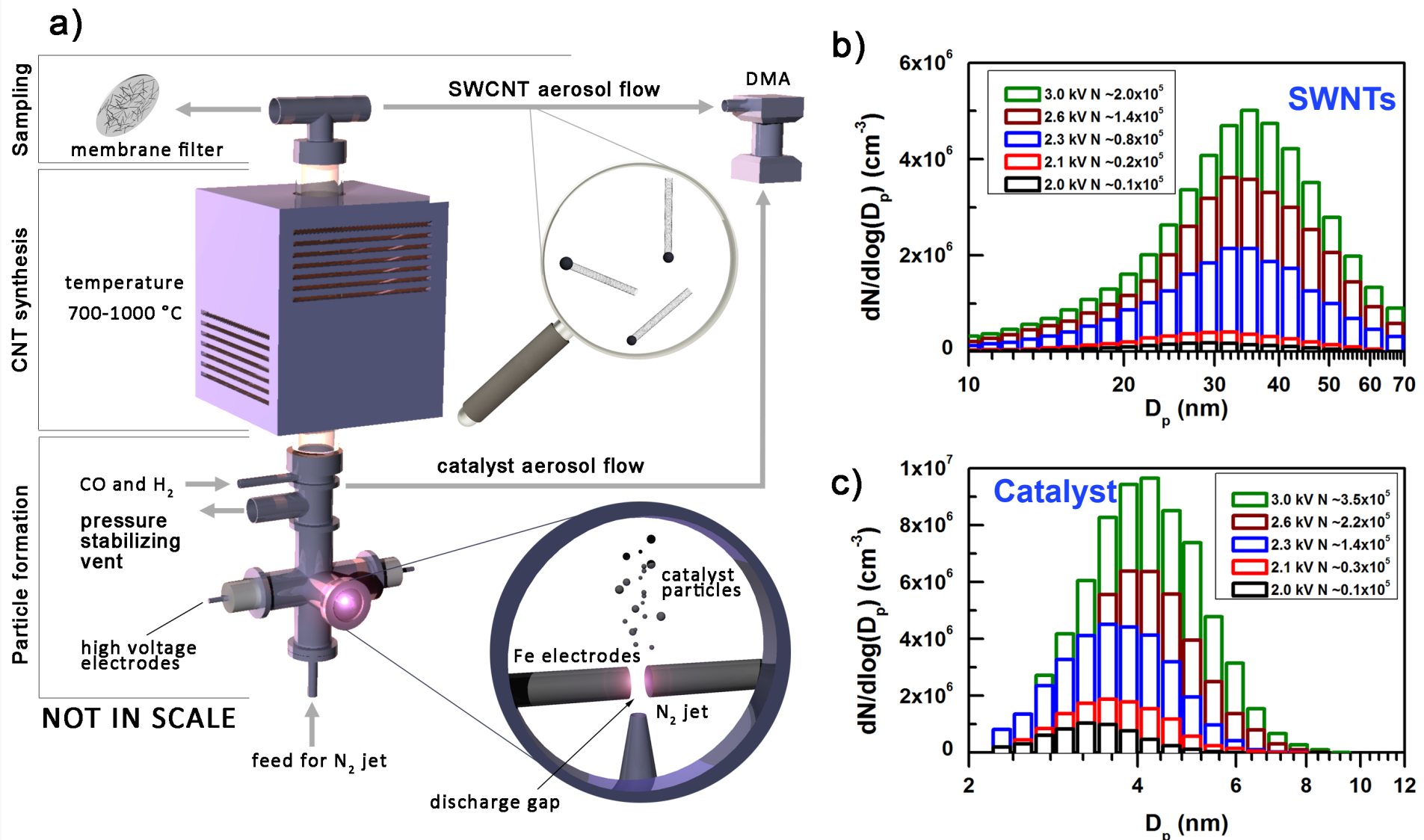


Nasibulin, Kaskela, Mustonen, Anisimov, Kauppinen, *et al.* (2011)

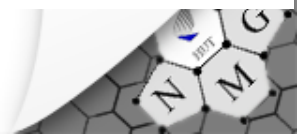
ACS Nano, 5(4), p.3214



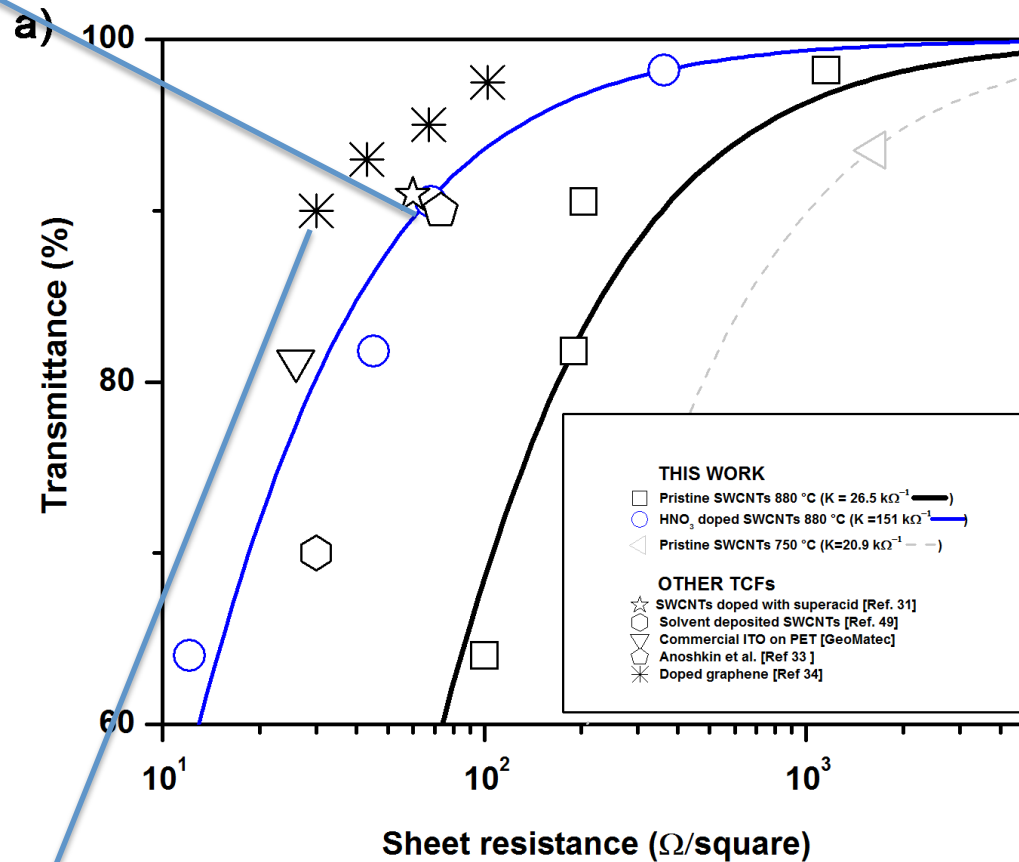
Novel spark discharge FC-CVD SWNT technology – separate catalyst formation and SWNT nucleation - bundling control



K. Mustonen et al. (2015) Submitted



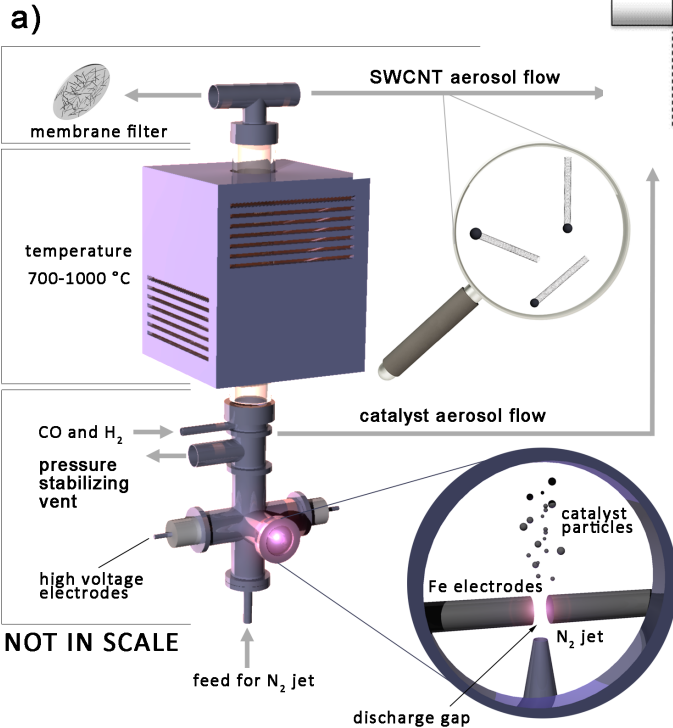
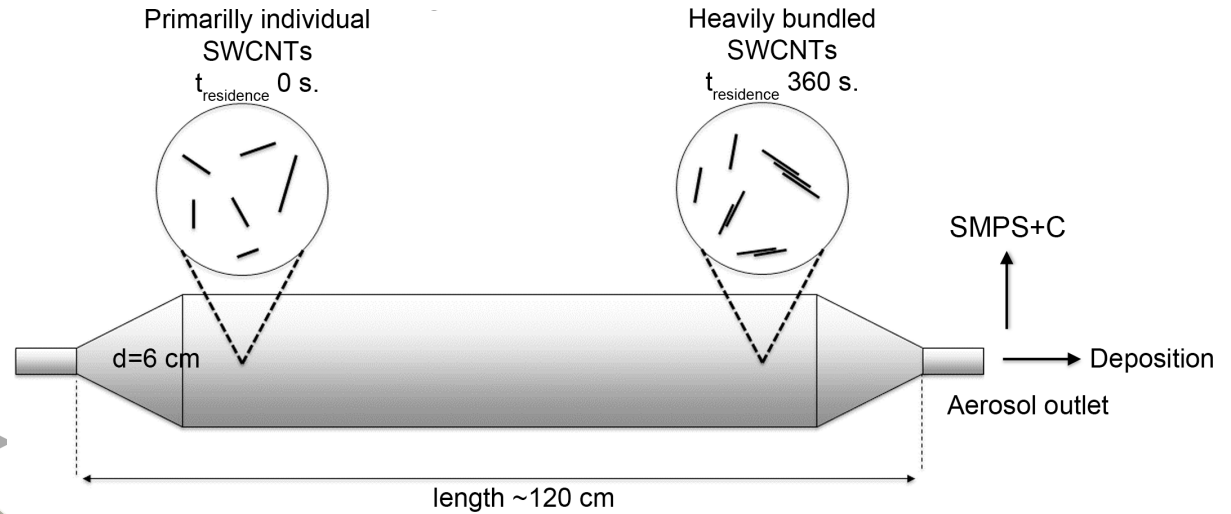
TCF with Individual tubes – length 4 microns – 60 ohms/sq @ 90 % T (HNO₃ doped)



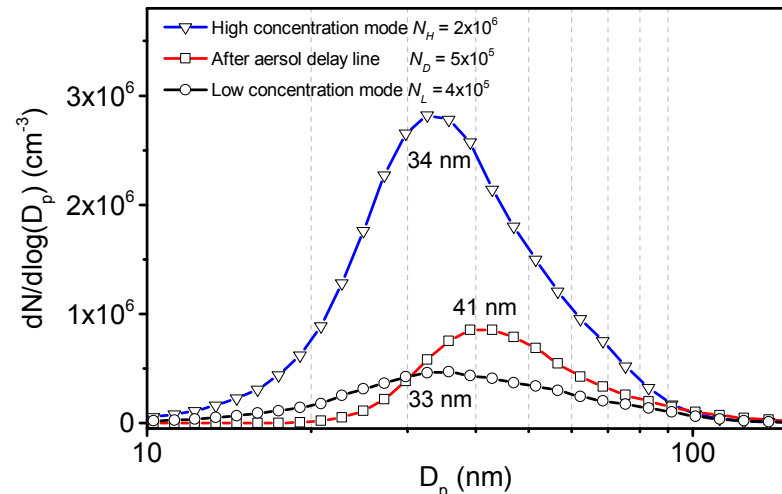
Note: Graphene * 30 ohms/sq @ 90 % T - has been transferred 4 times from Cu substrate

SWNT bundling in the laminar flow reactor – 0 to 360 s delay time.

Spark discharge Fe catalyst in N_2 - H_2 -CO FC-CVD – low and high SWNT number concentration



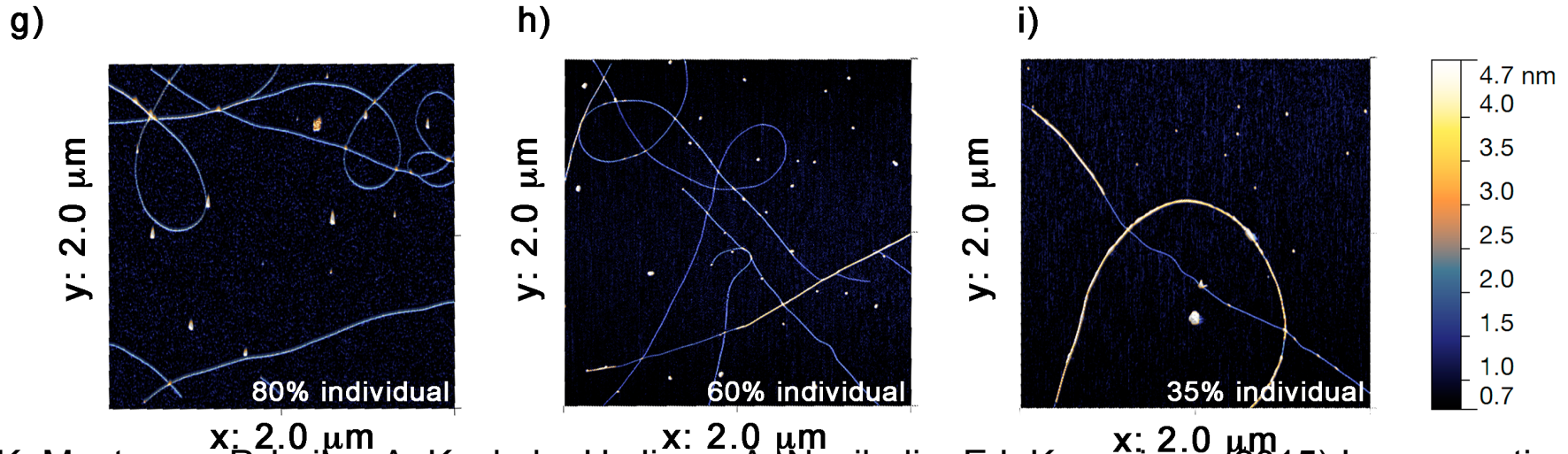
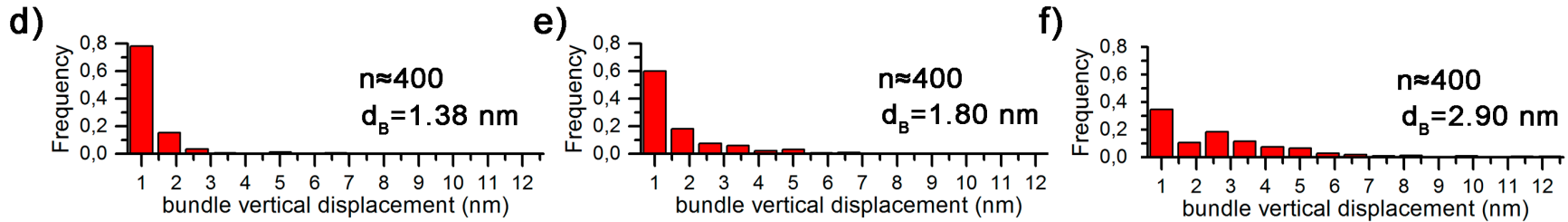
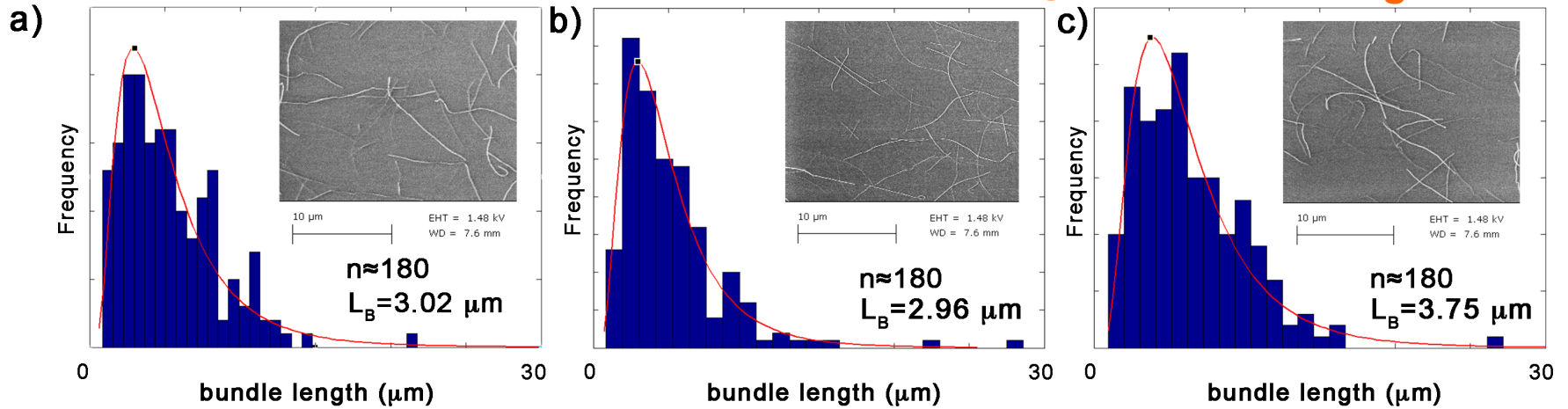
Gas phase SWNT number size distributions based on electrical mobility



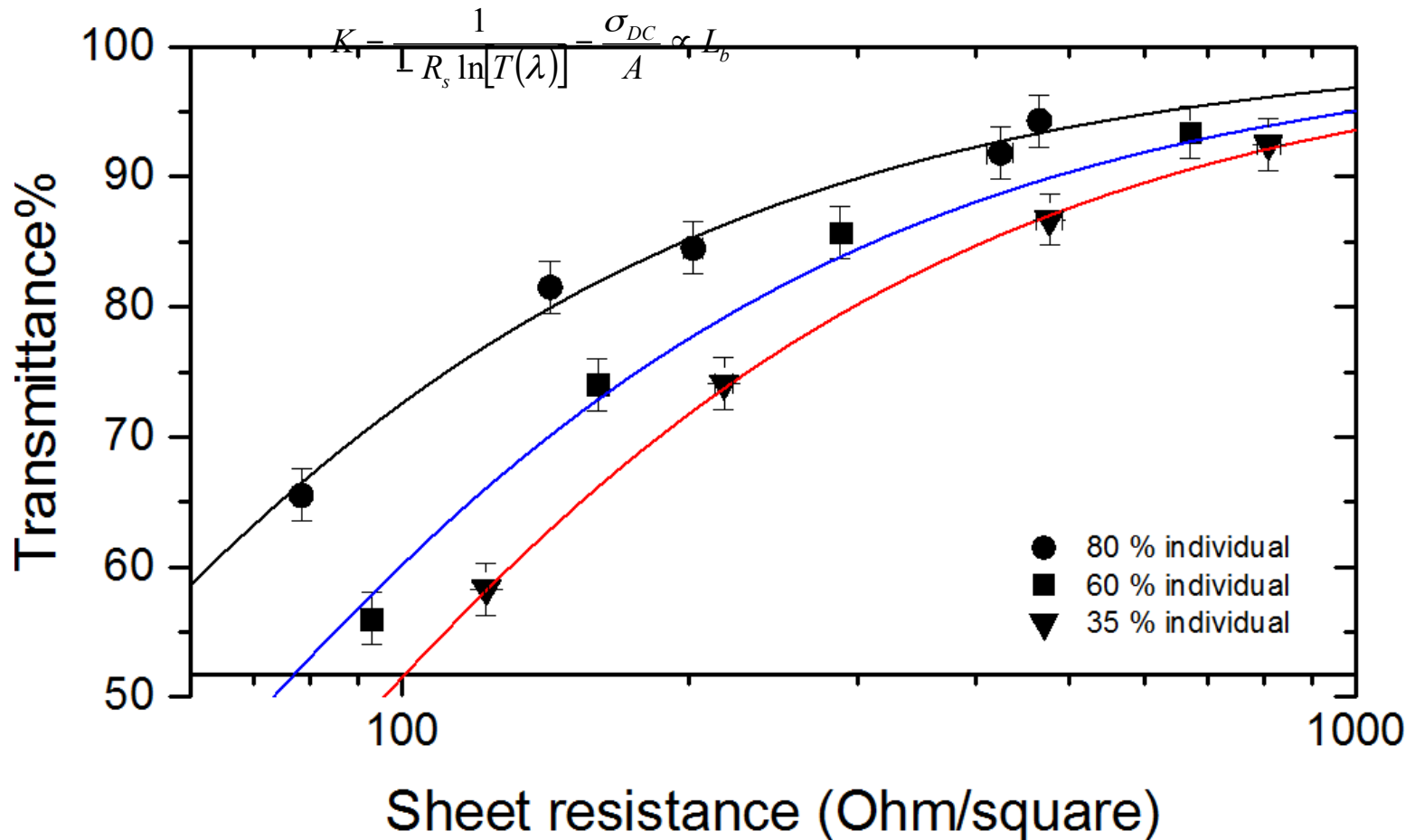
Low concentration
No additional bundling

High concentration
No additional bundling

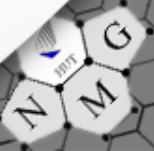
Low concentration
360 s bundling time



The effect of bundling on sheet resistance vs. transmittance – non-doped films



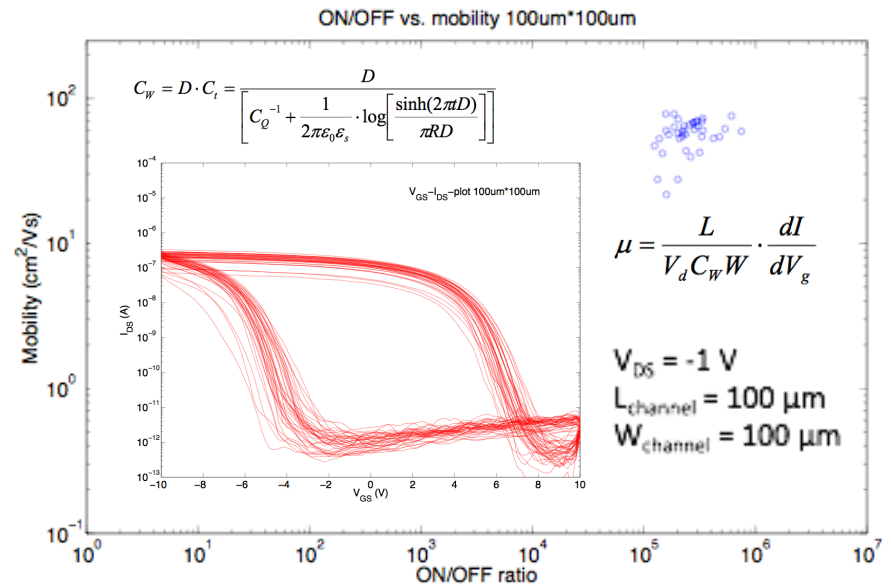
K. Mustonen, P. Laiho, A. Kaskela, H. Jiang, A. Nasibulin, E.I. Kauppinen (2015) In preparation



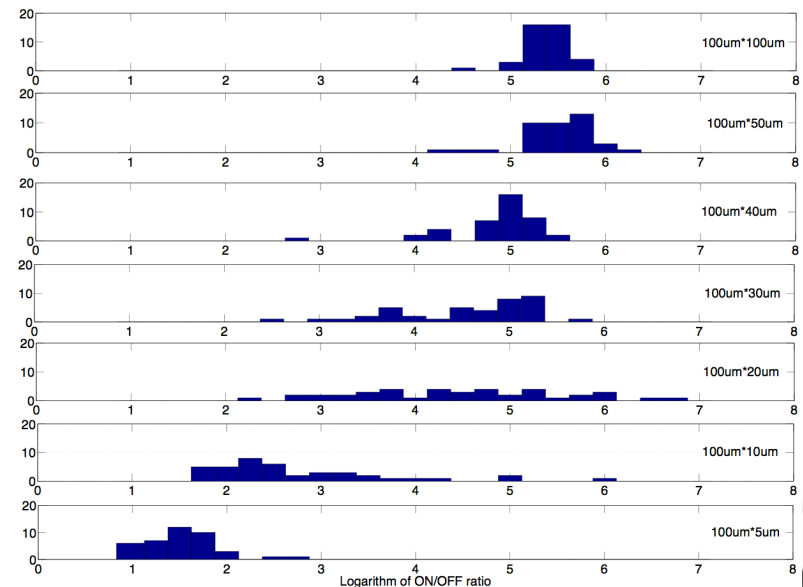
TFT-FETs

Spark FC- CVD SWNT random network via filter transfer

- Excellent SWCNT network uniformity
 - High device yield and controlled transfer characteristics
- The charge carrier mobility $\sim 100 \text{ cm}^2/\text{Vs}$ and typical ON/OFF ratios $> 10^5$
- Small ON current spread
- ON/OFF ratios scaling as function of channel length
 - SWCNT network uniformity approaches ideal random network with 1/3 metallic and 2/3 semi-conductive SWCNT

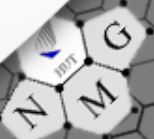


Kang et.al. Nature Nanotech, 2007.



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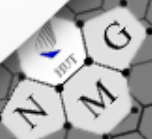
Companies following IRENA

From EU:

- Osram
- Nokia Oy
- Canatu Oy
- Fortum Oy
- Sefar AG
- Beneq Oy
- Amcor
- Eight19 Ltd

From Japan:

- Showa Denko K.K.
- Toray



ACKNOWLEDGEMENTS:

PRINTED TOUCH SENSORS USING CARBON NANOBUD[®] MATERIAL

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www.canatu.com

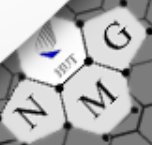


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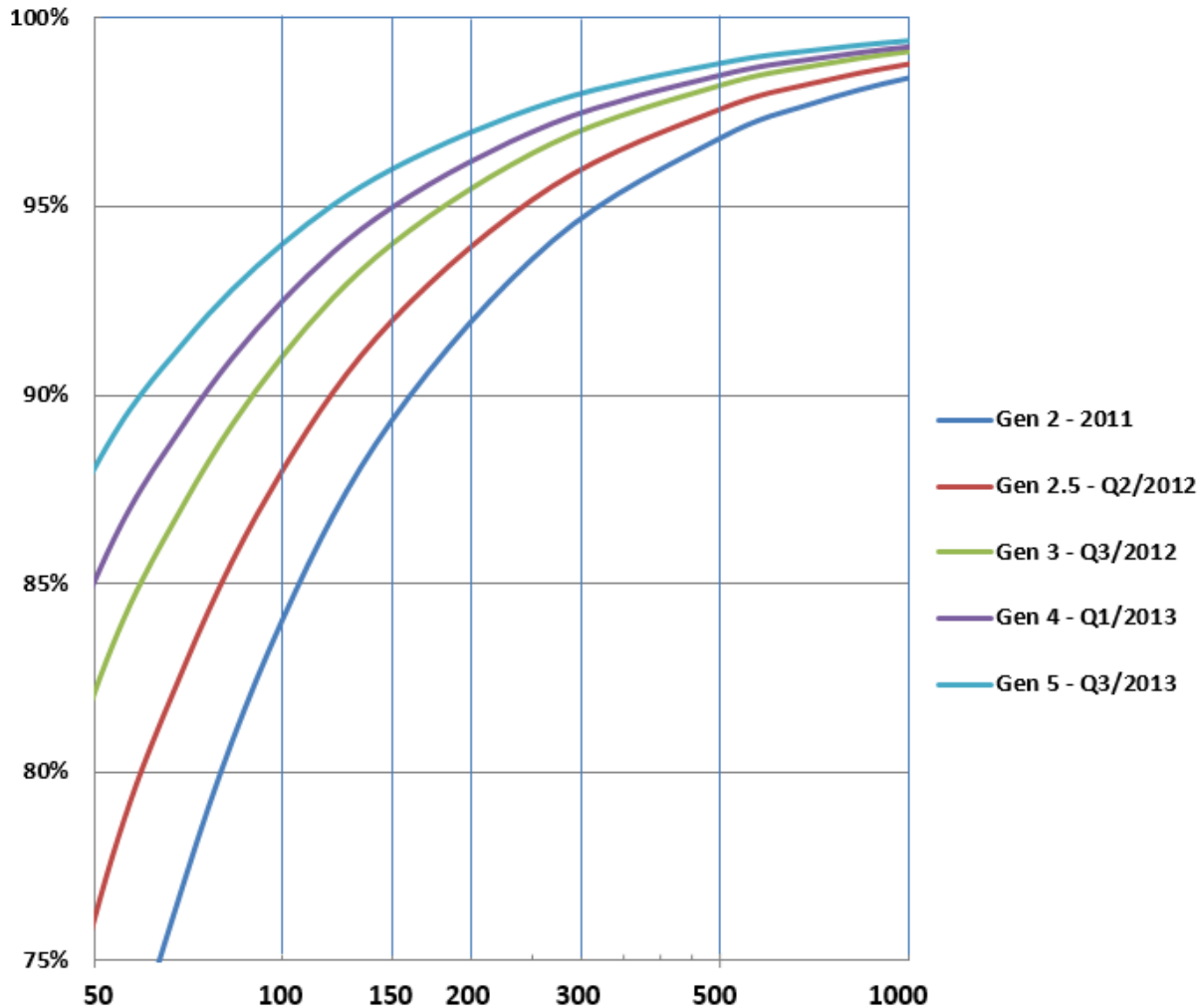
Touch the Future

Canatu's production facility

- In Helsinki, Finland
- Roll-to-roll 600mm wide CNB™ Films
- 1200 m² production space
- 400 m² clean room
- Canatu is
ISO 9001:2008 certified



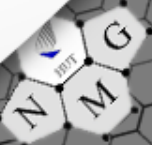
Commercially available by Canatu Oy: High transparency nanotube film - meeting ITO stability and uniformity specs



Examples:

100 Ω/\square at 94%
150 Ω/\square at 96%
270 Ω/\square at 98%

This is substrate-normalized
transmission:
T = 100% - CNB Absorbance





Haze comparison in touch modules

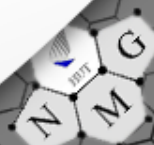
Intel measurements from 13.3"

Ultrabooks

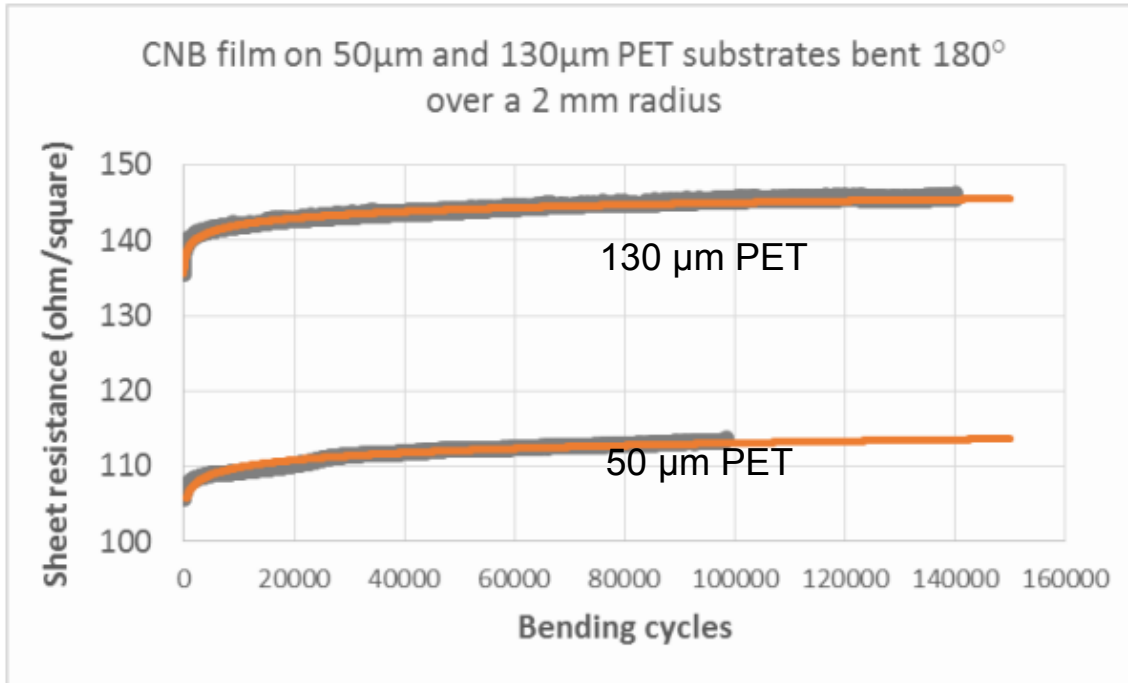
Touch Module	Type	Sensor	Haze (%)
Carbon <u>NanoBud</u>	CNB	GFF	0.6
ITO OGS (no index matching)	ITO	OGS	3.3
Silver nanowires Metal Mesh	Mesh	GFF	1.4
Silver Metal Mesh #1	Mesh	GFF	2.0
Copper Metal Mesh #1	Mesh	GF2	1.6
Copper Metal Mesh #2	Mesh	GF2	2.0
Silver Metal Mesh #2	Mesh	GF2	1.3
IPAD 4 (Air)	ITO	GF2	1.0



CNB has the lowest haze in the industry



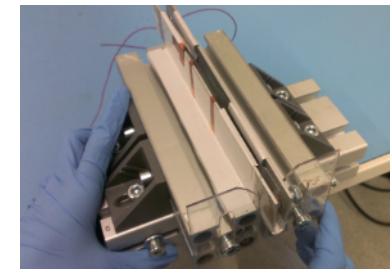
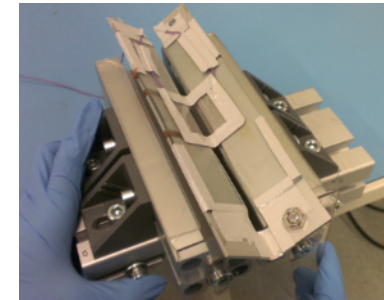
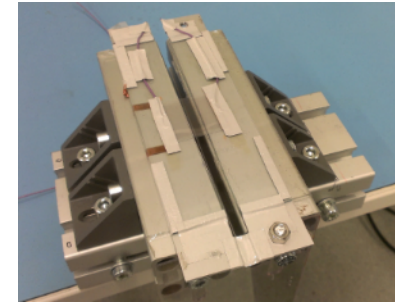
CNB Film lifetime bending test – touch sensors for *flexible devices*



Gray lines are raw values and orange lines are fitted values.

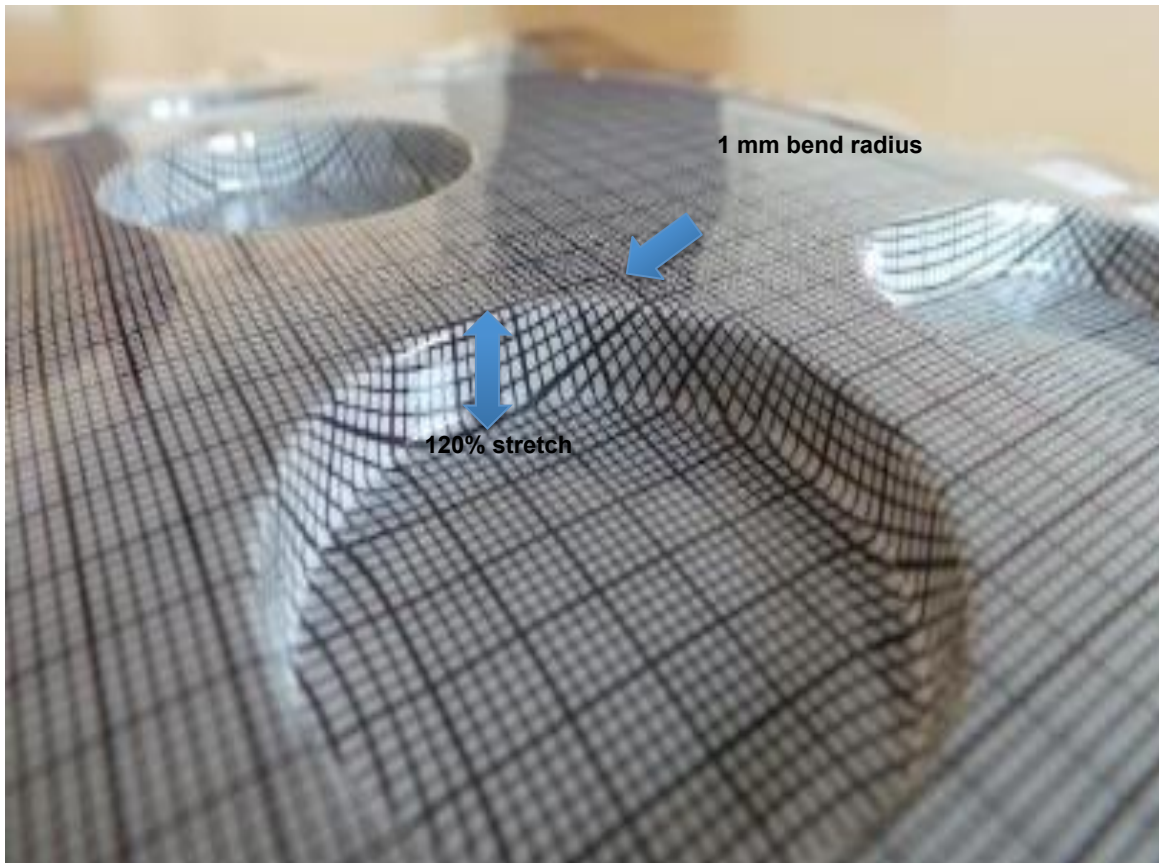
7% resistivity change at 2 mm bending radius over 140 k bending cycles.

CNB survives a lifetime of a foldable device.

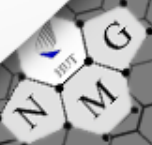


CNB™ films can be stretched

- Using Industry-standard forming and injection moulding processes: Pressure forming, Film Insert Molding (FIM)
- Locally stretched as much as 120%, bending radius 1 mm
 - CNB™ still remained conductive in the tested challenging forms



Bayer **MaterialScience**



OPEN POSITIONS! Department of Applied Physics **OPEN POSITIONS!**



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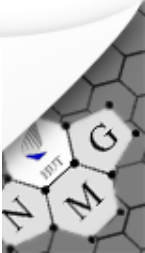
Dr. Toma Susi

<http://www.fyslab.hut.fi/nanomat/>



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Thank You Very Much for Your Attention !

